

Document title	Automated Ellipsometry-Reflectometry tool for 300 and 200 mm wafers
Réf. Chrono	DRT-LETI-DPFT-SMCP-LPMS-25-10-002363

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Informations pour la rédaction du Cahier des Charges à supprimer en fin de rédaction

CONSIGNE :

Ne pas supprimer les chapitres et sous-chapitres (cohérence avec Annexe A)

Mettre à jour la table des matières en fin de rédaction du Cahier des Charges

LEGENDE :

- Texte en noir => ne pas modifier
- Texte en bleu => à adapter

- Texte surligné en vert => consigne de remplissage, à supprimer en fin de rédaction

- Texte/tableau en fond grise => exemples dont le principe est à ré-utiliser

1 PURPOSE

This document describes the hardware, software and associated features related to the purchase of a thin film measurement tool, 300 mm (FOUP) and 200 mm (open cassette) capabilities and fully compatible with class 100 clean room environment.

The equipment shall include spectroscopic ellipsometry and spectroscopic reflectometry capabilities.

This tool shall allow consistently reliable and accurate thickness and optical properties determination of single layers and stacks of engineered substrates, responding to the following technologies : silicon-on-insulator (SOI) , strained silicon, strainedSOI, high-k materials, GaN, SiC, III-V materials etc.

It will also to measure reflectivity on optical filter.

Documents to be provided by the Contractor during the tender process

- ✓ The Contractor must complete and deliver to CEA-LETI **Appendix A: Summary of Contractor's comments** and put any comments in this section (the Contractor must not add any comments in the main text).
- ✓ The Contractor must complete and deliver to CEA-LETI **Appendix H: Datasheet for Tool Installation.**
- ✓ The Contractor must deliver to CEA-LETI the system footprint and dimension of all systems or sub systems
- ✓ The Contractor must deliver to CEA-LETI pre installation manual
- ✓ The Contractor must complete and deliver to CEA-LETI **Appendix I: Risk Identification Sheet**
- ✓ The Contractor must complete and deliver to CEA-LETI **Appendix J: SECS/GEM Compliance**
- ✓ The Contractor must complete and deliver to CEA-LETI **Appendix K: pedestal specification**

2 PROCESS OR MEASUREMENT SPECIFICATIONS

2.1 General specifications

The equipment will be a 300mm and 200 mm automated system, using mini environment(s) to ensure the integrity of wafer cleanliness.

The equipment shall include at least the following capabilities:

- Capa 1 : Spectroscopic ellipsometer with UV-VIS-NIR spectral range (at least cover 200 - 1700nm)
- Capa 2 : Spectroscopic reflectometer with UV-VIS spectral range (at least cover the 200 – 900nm)

All the specifications described in the following sub-sections and all the corresponding tests will be performed on 300 mm and 200 mm wafers provided by the supplier or LETI. The following specifications will be verified during pre-acceptance (PA) at supplier's site, acceptance at LETI's site (A) or warranty period at LETI's site (W). Any specification verified during PA and A tests must be stable and available all other the warranty period and might be checked at any time during W.

The tool specifications listed in the following sub-sections may be tested any time during the warranty period. The codes used in the specification's tables are listed in Table 1.

Table 1: List of the codes and related meaning used in the following sections of the document.

Code	Description
D	Description
C	Code
PA	Factory Acceptance
A	Acceptance
W	Warranty
S	Specification
P	Checking procedure
SR	Static Repeatability
DR	Reproducibility (Dynamic repeatability)
ST	Stability
T	Thickness
n	Refraction index; n_{633} : refraction index at $\lambda=633\text{nm}$
k	Extinction coefficient
R%	Reflectivity: method of measurement or value of reflectivity at one lambda
R	Reflectance: reflectivity spectrum
CD	Critical Dimension (nm)
HT	Pattern Height (nm)
SWA	Side Wide Angle (°)
SCS	Serial Cross-Solving OCD model solving (parameters injection solving)
PCS	Parallel Cross-Solving OCD model solving (linked parameters solving)

2.2 Substrates and stacks specifications

The equipment shall allow accurately measurement of, at least, the layers and stacks listed in Table 2. The ability of measuring such layers and stacks is part of the specifications of the equipment and may be tested any time during A and / or W period.

The tool must be compatible with the reliable measurement of SiO₂ thicknesses up to 6 µm using ellipsometry and up to 15 µm using reflectivity. The extension of this capability to the measurement of thick oxides or photoresists (up to 100 µm) is compulsory.

As the tool will feature a fixed angle of incidence (AOI), all the tests included in Chapter 0 must be run with fixed AOI in the data refinement process.

The Contractor will have to demonstrate its capacity to reach the specifications to which he complies, by presenting results obtained on the proposed tool.

Table 2: Compulsory capabilities of the equipment (could be tested any time during PA, A, W period).

Layer	Process window	Parameters to measure
SiC c-SiC on a-SiC c-SiC on polymer	5 < T < 10 µm Either on SiC or Si	T
III-V materials (InP/GaN...)	10 nm < T < 6µm Either on SiC or Si or III-V	T, uniaxial anisotropy
Thermal oxide, TEOS Oxinitride, Silicon nitride	1 nm < T < 60 µm	T,n,k
SOI	2 nm < T(top Si) < 400 nm 5 nm < T(Box) < 2 µm	T(each layer)including native oxide
Photoresists	10 nm < T < 100 µm Either on Si or on glass	T for the whole thickness range (n,k) @ 193 & 248 nm if T < 200 nm
Amorphous carbon	2 nm < T < 500 nm Deposition on silicon or on glass	T,n,k uniaxial anisotropy
Transparent Conductive Oxides (AZO,ITO,SnO2...)	10 nm < T < 200 nm Deposition on silicon or on glass	T,n,k including absorption in UV and NIR range
Piezoelectric materials (PZT...)	50 nm < T < 2 µm	T, uniaxial anisotropy
Optical filters	Deposition on silicon or on glass Total thickness up to 5 µm	reflectance spectrum from 200 nm to 1100 nm

Note that the tool must feature the appropriate filters so as to limit photon-induced degradation of photoresists.

The performances of the equipment will be evaluated by measuring the test wafers listed in

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Table 3. Suitable recipes and optimized parameters (number of points, models...) for measurement will be specifically developed by the supplier and shared with CEA-Leti for validation.

Table 3 : List of test wafers for optical properties, thickness & material

Table 3.1 : 200 mm wafer :

Slot	Stack	Substrate	Thickness	Measurement	Required test
2	SiC / aSi	pSiC	10 µm / 20 nm	T	{DR} (T)
3	GaN / SiO2	Si	500 nm / 200 nm	T	{DR} (T)
4	GaN / SiO2	pSiC LR	500 nm / 400 nm	T	{DR} (T)
6	SiO2	pSiC	30 nm	T	{DR} (T)
7	AlN / GaN/SiO2	Si	200 nm / 2000 nm / 2200 nm	T	{DR} (T)
20 (4P)	InP / SiN/SiO2/aSi/SiO2	Si	450 / 5 / 30 / 10 /1500 nm. 100 mm wafer on 200 mm Holder	T	{DR} (T)
25	RGB Filter	Glass	NA	R	-

Table 3.2 : 300 mm wafer :

Slot	Stack	Thickness	Measurement	Required test
1	Thermal SiO2/Si Sub	2 nm	T,n @ 633 nm R%@193 nm ,R%@248 nm	{DR,ST} (T,n,R%)
2		5 nm		
3		25 nm		
4		50 nm		
5		100 nm		
6		400 nm		
7		1 µm		
9	SiNx/Si sub	80 nm	T (n,k) @ 220, 633 nm	{DR,ST} (T,n,k)
10	SOI with BOX 2000nm	T(Si top):400 nm	T (native oxide, Si top and BOX)	{DR} (T_each layer)
11	SOI with BOX 145 nm	T(Si top):12 nm		
12	SOI with BOX 25 nm	T(Si top):12 nm		
14	SiGe Relaxed /Graded SiGe/Si	T SiGe Relaxed < 1µm T Graded SiGe ≈ 2µm 10 %<SiGe Top %<30 %	T (SiGe Relaxed) and Composition (SiGe Relaxed)	Nice to have a model
15	Si/ SiGe Relaxed (1µm)/Graded SiGe (2µm) /Si	T (Si) : 15 nm : 0.4%<Si strain< 1.2 %	Strained of Si and T	Provide a model
16	SiGe Relaxed /Si/SiO2/Si	0<T (SiGe)<300 nm T (Si) : 15 nm : T (SiO2) = 20 nm	T of SiGe and Si	Provide a model
19	Amorphous-C / Si Sub	100 nm	T Inplane and out-of-plane (n, k) @250, 400 and 633 nm	{DR} (T,n,k)
20	SOI with BOX 20 nm	T(Si top):15 nm 0.4%<Si strain< 1.2 %	Strained of Si and T	Provide a model
21	Band pass filter	Deposition on silicon; Total thickness = 1 µm	Reflectance spectrum	R
24	Resist/Si Sub	45µm	T	{DR} (T)
25	Resist/Si Sub	50 nm	T	UV blocking efficiency on SE and SR

Table 3.3 List of test wafers for Option 1

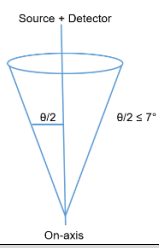
Morphological measurements (OCD).

Ref	Step	Mask/Target	Materials	Required test
101	Internal Si etch	FM line fields	Si, SiO2	{SR} CD, SWA, HT
102	STI at CMP or On-Etch	C28/ZACT1 C28/ZACT2	Si, SiO2, Nitride	CD, SWA, HT, SCS, PCS
103	Etch gate	C28/ZGAT	Si, SiO2, SiN, TiN, HfO2, Poly	{DR, SR} CD, SWA, HT

2.3 Inspections performances

HANDLING CONTROL	
D	TEST 1 : CROSS SLOTTED WAFER
C	PA/A/W
S	Cross slot detection when auditing
P	The Robot automatically maps the FOUP (300 mm) or cassette (200mm). All cross-slotted has to be detected. If a cross-slotted wafer is detected, the corresponding slot number has to be identified and it has to be impossible to select the cross-slotted wafer. Test will be done with 300 and 200 mm.
D	TEST 2 : CASSETTE RECOGNITION & MAPPING
C	PA/A/W
S	No hard data is generated
P	Test run with 300 mm wafers in FOUP and 200 mm wafers in cassette. Each load port is tested for wafer handling functionality. This includes: recognition of FOUP or cassette presence (with clear indicator of which is active), recognition of pre-mature removal, mapping of all FOUP and cassette slots, recognition of wafer in slot in all sizes and edge/notch orientations. Robot functionality for pick and place shall also be tested.
D	TEST 3 : MINIMUM EDGE EXCLUSION
C	A/W
S	< 1 mm
P	300 mm Si wafers with a SiO ₂ deposit shall be used for this test.
D	TEST 4 : POSITION REPEATABILITY
C	A/W
S	- Wafer positioning (angle) < 0.2° (3σ = standard deviation) - Wafer positioning (X,Y) < 140 μm (3σ) for X and Y axis - Stage: < 1 μm (3σ) for X and Y axis
P	This test will use a patterned wafer provided by the supplier. This test wafer is loaded and 2 sites will be chosen: one in the center of the wafer, one close to the edge. The X and Y coordinates of these sites are recorded manually. The movement from the center to the edge is performed by moving the X axis of the stage. The features will be visited 10 times with load/unload between each measurement. The wafer positioning repeatability (X, Y) is deduced from the dispersion of the coordinates recorded for this center site. The wafer rotation angle repeatability is deduced from the coordinates of both sites. To evaluate the stage repeatability, 2 sites are defined on the surface of the 300 mm wafer. The wafer is aligned to remove the wafer rotation. The coordinates of the 2 defined sites are recorded. These 2 sites are then visited 30 times without unload of the wafer; the variance of the recorded coordinates is calculated.
D	TEST 5 : SPOT SIZE
C	PA/A/W
S	- Ellipsometry: ability to measure in 50 μm x 50 μm TBOX - Reflectometry: ability to measure in 50 μm x 50 μm TBOX
P	This test will use patterned wafers provided by the supplier. The goal of this test is to check the size of the different spots that may be used during a measurement sequence. For each measurement technology (ellipsometry, reflectometry), the tool shall be able to measure into a T-Box (pad or trench) using site-by-site pattern recognition (measure in 50 μm x 50 μm TBOX) The spot length (SL) will be estimated by running a line scan measurement in a 100 x 100 μm T-Box, from the left to the right edge by 2 μm steps. The spot length can be assimilated to the sum of the left and right side length to results stabilization (within reproducibility specifications). The same procedure will be performed from the bottom to the top of the T-Box to estimate the spot height (SH).

D	TEST 6 : PATTERN RECOGNITION TEST
C	PA/A/W
S	Failure rate < 0.05%
P	This test will use patterned wafers provided by the supplier. This test aims at evaluating the measurement errors due to pattern recognition issues. Spectroscopic ellipsometry and Spectroscopic reflectometry technique will be used for this test. One measurement per die will be performed, 9 dies per wafer. The sites (SE:50 μm x 50 μm T-Box and SR:50 μm x 50 μm T-Box) will be measured. The test passes if: - No wafer is rejected due to auto focus or pre-alignment - No wafer transfer problem occurs during these tests (transfer, pre-alignment, alignment and measurement). An overnight test will be run on 5 wafers in order to obtain sufficient data about pattern recognition.
D	TEST 7 : SPOT PLACEMENT REPEATABILITY
C	A/W
S	For SE technique: - ability to measure in 50 μm x 50 μm TBOX 3* Max[(σ20)] < 0.05% For SR technique: - ability to measure in 50 μm x 50 μm TBOX 3* Max[(σ20)] < 0.05%
P	This test will use a patterned wafer provided by the supplier. This wafer will feature (50 μm x 50 μm (SE) and 50 μm x 50 μm (SR)) TBOX with SiO₂/Si sub stacking. 13 sites will be chosen on patterned wafer in order to cover center and edge of the wafer. The position of the different sites will be taught. The 13-sites measurement sequence (with global alignment and not site-by-site alignment) will be run 20 times successively with unloading the wafer between each set of 13 measurements. No measurement error shall occur. For each point, the thickness T of the SiO₂ layer will be monitored: the mean and standard deviation (σ20) will be calculated for each set of 20 data (13 sets for each wafer). For each wafer, the highest value of σ20 over the 13 sets of data (Max[(σ20)]) will be calculated.
D	TEST 8 : THROUGHPUT
C	A/W
S	For 200 mm wafers Ellipsometry - throughput > 60 wph (wafer per hour) for monitor wafers - throughput > 50 wph for patterned wafers with site-by-site alignment Reflectometry - throughput > 60 wph for monitor wafers - throughput > 50 wph for patterned wafers with site-by-site alignment
P	The throughput evaluation will use 200 mm wafers with thermal SiO₂ / Si bulk stack. Both single wafer throughput and throughput for a full FOUP (or cassette) of 25 wafers are measured. Throughput test starts when the start button is pushed (the FOUP/cassette is docking) until the last wafer measurement is completed and the FOUP/cassette is undocked. Throughput will be measured by using a 5-site pattern for the different measurement techniques on monitor and pattern wafers. The throughput will be determined by following procedure: Single wafer throughput: one wafer is loaded in slot 1, the test is performed 10 times and the mean of the time is calculated. Full FOUP throughput is determined by using 5 wafers loaded in slot #1, 7, 13, 19 and 25. The result for a complete FOUP is calculated by subtracting the time for measuring the single wafer (calculated previously) from the total measurement time, multiplying this time by 6 and adding this time to the measurement time of a single wafer. A time chart of the different phases (FOUP load, pre-alignment, measurement time...) will be provided.

D	TEST 9 : INDEX REFRACTION UNIFORMITY / ELLIPSOmetry
C	PA/A/W
S	For each run, the range of index refraction over 49 points (Max – min) must be less than 0.007
P	Test wafer 5 (300 mm) will be used The test will use a blanket wafer of 100 nm SiO₂/Si sub stacking. A circular mapping with 49 pts and edge exclusion of 3 mm will be used. 5 measurements will be made Each measurement sequence shall include the wafer loading and pre-alignment, the focus optimization, and the measurement itself. The parameters to monitor are: • T for oxide layers • n @ 633 nm
D	TEST 10 : Design of AOI for reflectivity
C	PA/A/W
S	For the SR module, in case an on-axis geometry (focused beam, see graph below) is suggested by the supplier as the best technical option, the half-angle ($\theta/2$) should not exceed 7° in any case. 
D	TEST 11 : SPLIT PLACEMENT ACCURACY ON PIXELS
C	PA/A/W
S	• Reflectance spectrum on optical filters : Red, Blue, Green and Infra Red • Pixel sizes: 100 µm (taken as reference) and 50 µm • The reflectance data must show no shift in wavelength position larger than ± 1 nm for the whole spectral range • The reflectance spectrum must show no shift in reflectivity larger than ± 0.5 % • More than 99% of the energy of the beam is included in the pixel (for 100 µm and 50 µm pixel sizes)
P	Test wafer 25 (200 mm) will be used Reflectance spectrum on optical filters : Red, Blue, Green and Infra Red For each filter (Red, Blue, Green and Infra Red) : the spectrum reflectance obtained on the pixel 100 µm will be taken as the reference spectrum. The reflectance spectrum for 50 µm pixel size will be compared to the reference spectrum. The reflectance data must show no shift in wavelength position larger than ± 1 nm for the whole spectral range. The reflectance spectrum must show no shift in reflectivity larger than ± 0.5 % The supplier will demonstrate that more than 99% of the energy of the beam is included in the pixel (for 50 µm pixel sizes). The related protocol must be commonly agreed by the supplier and CEA-LETI.

ITERATIVE MEASUREMENT CAPABILITY	
D	TEST 12 : Fully automated “iterative measurement capability”.
C	A/W
D	The tool must include a fully automated “iterative measurement capability”. The aim of this function is to feed the data reduction process of SE or SR data at measurement step N with the quantitative data (thickness) deduced from the measurement at step (N-1). This function must apply for mapping of both blanket and patterned wafers. For each point of the mapping, the thickness (or thicknesses in case of stacks) of the layer(s) measured at step (N-1) will be automatically set as fixed values in the modeling at step N. The “iterative measurement capability” must include some flexibility : • The technique used at step N may differ from the one at step (N-1), provided that the measurement is performed on the same tool. For instance, SE may be used at step (N-1), then SR at step N • The spectral range at step N may differ from the one at step (N-1) • The modeling strategy may be different for steps N and (N-1) : for instance, Fourier transform analysis may be used at step (N-1) in order to deduce the thickness of very thick stacks, and standard modeling (stack-based) may be then used at step N • As this technique should apply at the different steps of the process, step (N-1) may be on blanket wafer, then step N on pattern wafer • The coordinates of the measurement points should be defined within a certain (recipe defined) range so as to allow, for instance, for measurement in different TBox @ step N, whereas the measurement at step (N-1) was performed on blanket wafer. A unique batch identifier must be used for all the measurement steps of each wafer set.
S	• T1 measured in M1 = T1 measured in M2 and M3. • T2 measured in M2 = T2 measured in M3. • The display of each Tx will be appeared for each step of measurement.
P	• Layer deposition of SiO2 PECVD 100 nm with LETI Tool • Measurement (M1) of this oxide. Thickness 1 (T1) • Layer deposition of SiN PECVD 300 nm with LETI TOOL • Measurement (M2) of this SiN. Thickness 2 (T2) with T1 fixed • Layer deposition of SiO2 PECVD 800 nm with LETI Tool • Measurement (M3) of this SiO2. Thickness 3 (T3) with T1 and T2 fixed • All measurement will be made in 9 pts, the thickness of each point of measurement will be monitored

DYNAMIC REPEATABILITY	
D	TEST 13 : DYNAMIC REPEATABILITY ON OXIDE AND NITRIDE: ELLIPSOMETRY
C	PA/A/W
S	- Oxide layers: 2 nm $\leq$ T $\leq$ 15 nm: $3.\sigma_{rep} < 0.02$ nm 15 nm $<$ T $<$ 30 nm: $3.\sigma_{rep} < 0.03$ nm 30 nm $<$ T $<$ 200 nm: $3.\sigma_{rep} < 0.05$ nm 200 nm $<$ T $<$ 1 μm: $3.\sigma_{rep} < 0.025$ % - n @ 633 nm (for T $>$ 40 nm): $3.\sigma_{rep} < 0.0015$ - Nitride layer: - T: $3.\sigma_{rep} < 0.05$ nm (n,k) @220 nm & 633 nm: $3.\sigma_{rep} < 0.0015$
P	Test wafers 1 to 9 (300 mm) will be used. 30 measurements of each wafer will be made, in the same location (near the centre). Each measurement sequence shall include the wafer loading and pre-alignment, the focus optimization, and the measurement itself. The parameters to monitor are: - T for all oxide layers (ref 1 to 8) - T and n @ 633 nm for oxide layers thicker than 20 nm grown on blanket wafers (ref 3 to 7) - T, (n,k) @ 193, 250 and 633 nm for the nitride wafer (ref 9) For each wafer, the mean and standard deviation (σ_{rep}) of these data are calculated. The data will be plotted to validate the assumption of a normal distribution with no trends.
D	TEST 14 : DYNAMIC REPEATABILITY ON OXIDE: REFLECTOMETRY
C	PA/A/W
S	- Thickness measurement: 60 nm $<$ T $<$ 200 nm: $3.\sigma_{rep} < 0.08$ nm 200 nm $<$ T $<$ 1 μm: $3.\sigma_{rep} < 0.05$ % - Normalized reflectivity measurement: - R @ 193 nm : $3.\sigma_{rep} < 0.01$ - R @ 248 nm : $3.\sigma_{rep} < 0.005$ - R @ 632 nm : $3.\sigma_{rep} < 0.005$ - R @ 1000 nm : $3.\sigma_{rep} < 0.005$
P	Test wafers 5 to 7 (300 mm) will be used. 30 measurements of each wafer will be made, in the same location (near the centre). Each measurement sequence shall include the wafer loading and pre-alignment, the focus optimization, and the measurement itself. The parameters to monitor are: - T - Normalized reflectivity For each wafer, the mean and standard deviation (σ_{rep}) of these data are calculated. The data will be plotted to validate the assumption of a normal distribution with no trends.
D	TEST 15 : DYNAMIC REPEATABILITY ON SOI: ELLIPSOMETRY
C	PA/A/W
S	- Top oxide layer: $3.\sigma_{rep} < 0.05$ nm - Top silicon layer: $3.\sigma_{rep} < 0.1$ nm - BOX layer: $3.\sigma_{rep} < 0.1$ nm
P	Test wafers 10 to 12 (300 mm) will be used. 30 measurements of each wafer will be made, in the same location (near the centre). Each measurement sequence shall include the wafer loading and pre-alignment, the focus optimization, and the measurement itself. The parameters to monitor are: - T of top oxide layer - T of top silicon - T of the BOX For each wafer, the mean and standard deviation (σ_{rep}) of these data are calculated. The data will be plotted to validate the assumption of a normal distribution with no trends.

D	TEST 16 : DYNAMIC REPEATABILITY ON AMORPHOUS-CARBON ELLIPSOMETRY	
C	PA/A/W	
S	- a-C layer: - T of amorphous carbone layer $3.\sigma_{rep} < 0.05 \text{ nm}$ - In plane, Out plane (n,k) $3.\sigma_{rep} < 0.0015$	
P	Test wafer 19 (300 mm) will be used. 30 measurements will be made, in the same location (near the centre). Each measurement sequence shall include the wafer loading and pre-alignment, the focus optimization, and the measurement itself. The parameters to monitor are: - T of a-C layer - In-plane and out-of-plane (n, k) @ 250, 400 and 633 nm The mean and standard deviation (σ_{rep}) of these data are calculated. The data will be plotted to validate the assumption of a normal distribution with no trends.	
D	TEST 17 : DYNAMIC REPEATABILITY ON RESIST: REFLECTOMETRY	
C	PA/A/W	
S	T(Resist) : $3.\sigma_{rep} < 0.1 \%$	
P	Test wafer 24 (300 mm) will be used. 30 measurements of each wafer will be made, in the same location (near the centre). Each measurement sequence shall include the wafer loading and pre-alignment, the focus optimization, and the measurement itself. The parameter to monitor is: T of the resist layer The mean and standard deviation (σ_{rep}) of these data are calculated. The data will be plotted to validate the assumption of a normal distribution with no trends.	
D	TEST 18 : DYNAMIC REPEATABILITY ON STACK SiC: REFLECTOMETRY	
C	PA/A/W	
S	- SiC /aSi / pSiC substrat: - T of SiC $3. \sigma_{rep} < 0.1\%$	
P	Test wafer 2 (200 mm) will be used. 30 measurements will be made, in the same location (near the centre). Each measurement sequence shall include the wafer loading and pre-alignment, the focus optimization, and the measurement itself. The parameters to monitor are: T of SiC The mean and standard deviation (σ_{rep}) of these data are calculated. The data will be plotted to validate the assumption of a normal distribution with no trends.	
D	TEST 19 : DYNAMIC REPEATABILITY ON STACK GAN: ELLIPSOMETRY	
C	PA/A/W	
S	- GaN and SiO2 layers: - T of GaN $3. \sigma_{rep} < 0.5\%$ - T of SiO2 $3. \sigma_{rep} < 0.5\%$	
P	Test wafer 3 and 4 (200 mm) will be used. 30 measurements will be made, in the same location (near the centre). Each measurement sequence shall include the wafer loading and pre-alignment, the focus optimization, and the measurement itself. The parameters to monitor are: T of each layers The mean and standard deviation (σ_{rep}) of these data are calculated. The data will be plotted to validate the assumption of a normal distribution with no trends.	

D	TEST 20 : DYNAMIC REPEATABILITY ON SiO2 ON SiC SUBSTRAT: ELLIPSOMETRY
C	PA/A/W
S	- SiO2 layer: - T of SiO2 3. $\sigma_{rep} < 0.5$ nm
P	Test wafer 6 (200 mm) will be used. 30 measurements will be made, in the same location (near the centre). Each measurement sequence shall include the wafer loading and pre-alignment, the focus optimization, and the measurement itself. The parameters to monitor are: T of SiO2 layer The mean and standard deviation (σ_{rep}) of these data are calculated. The data will be plotted to validate the assumption of a normal distribution with no trends.
D	TEST 21 : DYNAMIC REPEATABILITY ON ALN/GAN STACK: ELLIPSOMETRY
C	PA/A/W
S	- AlN / GaN / SiO2 layers: - T of AlN 3. $\sigma_{rep} < 1$ nm - T of GaN and SiO2 3. $\sigma_{rep} < 0.7$ %
P	Test wafer 7 (200 mm) will be used. 30 measurements will be made, in the same location (near the centre). Each measurement sequence shall include the wafer loading and pre-alignment, the focus optimization, and the measurement itself. The parameters to monitor are: T of each layers The mean and standard deviation (σ_{rep}) of these data are calculated. The data will be plotted to validate the assumption of a normal distribution with no trends.
D	TEST 22 : DYNAMIC REPEATABILITY ON INP STACK: ELLIPSOMETRY
C	A/W
S	- InP / SiN/SiO2/aSi/SiO2 layers : - T of InP 3$\sigma_{rep} < 2$ nm - T of SiN 3$\sigma_{rep} < 0.1$ nm - T of SiO2 3$\sigma_{rep} < 0.1$ nm - T of aSi - fixed - T of SiO2 3$\sigma_{rep} < 2$ nm
P	Test wafer 4P (100 mm wafer on 200 mm holder) will be used. 30 measurements will be made, in the same location (near the centre). Each measurement sequence shall include the wafer loading and pre-alignment, the focus optimization, and the measurement itself. The parameters to monitor are: T of each layers The mean and standard deviation (σ_{rep}) of these data are calculated. The data will be plotted to validate the assumption of a normal distribution with no trends.
D	TEST 23 : UV BLOCKING
C	PA/A/W
S	- Resist layer: - T of Resist layer 3.$\sigma_{rep} < 0.05$ nm
P	Test wafer 25 (300 mm) will be used. 30 measurements will be made, in the same location (near the centre). Each measurement sequence shall include the wafer loading and pre-alignment, the focus optimization, and the measurement itself. The parameters to monitor are: T of Resist layer The mean and standard deviation (σ_{rep}) of these data are calculated. The data will be plotted to validate the assumption of a normal distribution with no trends. Both SE and SR measurements will be performed. For each technique the appropriate filter will be used to block the contribution of UV range. No visual damage on the resist shall be observed after the measurement sequence.

ACCURACY	
D	TEST 24 : ACCURACY ON OXIDE: ELLIPSOMETRY AND REFLECTOMETRY
C	A/W
S	- Ellipsometry: 1.5 nm < T < 12 nm: accuracy < 0.1 nm 12 nm < T < 30 nm: accuracy < 0.1 nm 30 nm < T < 1 µm: accuracy < 0.2% - Reflectometry: 50 nm < T < 1 µm: accuracy < 0.1 nm or 0.2%
P	Accuracy is measured by comparing the system's measurement of a standard single layer oxide film on a Si wafer to the film's nominal thickness. 9 sites are measured within a 2 mm diameter and the average value is calculated. Accuracy = Abs(average of the measured values - certified value). When the accuracy is found to be within the uncertainty range of the standard, the system is considered calibrated and accurate for this measurement. NIST traceable standards will be used for this test. AMC removal will follow NIST BKM (230°C, 4 minutes, measurement within 30 minutes).
D	TEST 25 : MATCHING WITH A GOLDEN TOOL : REFRACTIVE INDEX
C	A/W
S	Abs(golden tool value – tool under test value) < 0.0035 for each wafer
P	Wafers references 4 to 7 (300 mm) will be used for this test. The golden tool for index measurement will be the Woollam M2000 tool installed in LETI 41 building. Samples will be measured, on the golden tool, 5 times in the centre without moving the stage. Average values will be recorded. The same test procedure will be repeated on the tool under testing and the same type of data will be recorded. The data refinement will be based on the following stack: Cauchy/ntve_jaw(1nm)/Si_jaw substrate. See [C. M. Herzinger et al, J. Appl. Phys. 83, (1998) 3323] for ntve_jaw and Si_jaw dispersion laws. Difference of mean value for each sample will be calculated.
D	TEST 26 : MATCHING WITH A GOLDEN TOOL: THICKNESS
C	A/W
S	Abs(golden tool value – tool under test value) < Max(0.06 nm; 0.6%.T _{oxide}) for each wafer
P	This test aims at comparing the performances of the tool under testing with an ellipsometer, already installed in the fab that will be considered as a golden tool. The golden tool will be either the NANOMETRICS ATLAS XP+ tool installed in LETI 41 building. Wafers references 1 to 7 (300 mm) will be used for this test. Samples will be measured, on the golden tool, 30 times in the centre without moving the stage. Average values will be recorded. The same test procedure will be repeated on the tool under testing and the same type of data will be recorded. Difference of mean value for each sample will be calculated.
D	TEST 27 : MATCHING WITH A GOLDEN TOOL: REFLECTANCE
C	A/W
S	- Wavelength position accuracy: - Whole spectral range : < +/- 0.1 nm - Reflectance accuracy: - Reflectance of the golden tool- Reflectance measured on the tool < 0.5% for the whole spectral range
P	Test wafer 21 (300 mm) will be used This test aims at comparing the performances of the tool under testing with spectroscopic reflectometer, already installed in the fab that will be considered as a golden tool. The golden tool will be the Agilent CARRY 7000A in LETI 51B building. Samples will be measured, on the golden tool, 10 times in the centre without moving the stage. The same test procedure will be repeated on the tool under testing and the same type of data will be recorded.

STABILITY	
D	TEST 28 : SHORT TERM STABILITY
C	PA/A/W
S	- Ellipsometry: - Thickness measurement: 2 nm ≤ T ≤ 10 nm: stability < 0.025 nm 10 nm < T < 30 nm: stability < 0.04 nm 30 nm < T < nm: stability < 0.15 nm 200 nm < T < 1 μm: stability < 0.08 % - Nitride optical index (n, k) measurement @ 220 and 633 nm: (n, k) @ 220 & 633nm: stability < 0.002 - Silicon oxide optical index n measurement @ 633 nm, for T > 40 nm: - n @ 633 nm: stability < 0.002 - Reflectometry (Thickness measurement): 50 nm < T < 200 nm: stability < 0.25 nm 200 nm < T < 1 μm: stability < 0.25%
P	Test wafers 1 to 9 (300 mm) shall be used for this test. The short-term stability is measured by performing a series of dynamic repeatability tests (3 times per day during 3 days). The short-term stability is defined as the 3-sigma standard deviation of the mean values of the series of test.
D	TEST 29 : LONG TERM STABILITY
C	A/W
S	- Ellipsometry: - Thickness measurement: 2 nm ≤ T ≤ 10 nm: stability < 0.05 nm 10 nm < T < 30 nm: stability < 0.05 nm 30 nm < T < 200 nm: stability < 0.15 nm 200 nm < T < 1 μm: stability < 0.09% - Nitride optical index (n, k) measurement @ 220nm and 633nm : (n, k) @ 220 & 633nm: stability < 0.003 - Silicon oxide optical index n measurement @ 633nm, for T > 40 nm : - n @ 633nm: stability < 0.003 - Reflectometry (Thickness measurement): 50 nm < T < 200 nm : stability < 0.3 nm 200 nm < T < 1 μm : stability < 0.3%
P	Test wafers 1 to 9 (300 mm) shall be used for this test. The long-term stability is measured by performing a series of dynamic repeatability tests (once a day during 10 days). The long-term stability is defined as the 3-sigma standard deviation of the mean values of the series of test.

STRAINED SOI SPECIFIC METRICS
Providing a model to determine the thickness and stress of silicon would be beneficial. Reference wafers can be supplied for building the model.
TEST 30 : SILICON ON INSULATOR STRAINED AND THICKNESS MEASUREMENT
A/W
Silicon dispersion is modified by strain: the ellipsometer and / or reflectometer tool can allow to build a model providing as a fit output the following parameters: - Top Si thickness, target = 12 nm - SiO2 thickness, target = 20 nm - Top Si strain = 0.4 % < target < 1.2 % Fit parameters can be optimized based on an offline metrology Test wafers 20 (300 mm) shall be used for this test.

TEST 31 : SILICON STRAINED AND THICKNESS MEASUREMENT Si epitaxial layer grown on relaxed SiGe layer to induce strain
A/W
Silicon dispersion is modified by strain: the ellipsometer and / or reflectometer tool can allow to build a model providing as a fit output the following parameters: ○ Strained Si thickness, target = 15 nm ○ Si strain = 0.4 %<target< 1.2 % Fit parameters can be optimized based on an offline metrology
Test wafers 15 (300 mm) shall be used for this test.
TEST 32 : RELAXED SIGE THICKNESS MEASUREMENT on SOI structure
A/W
Target is to build a model enabling the accurate fit of both layers allowing to estimate separately SiGe and SiGe Thickness ○ $0 < T(\text{SiGe}) < 300 \text{ nm}$ ○ $T(\text{Si target}) = 15 \text{ nm}$
Test wafers 16 (300 mm) shall be used for this test.

SIGE THICKNESS AND COMPOSITION
Nice to have a model to determine the thickness and concentration of SiGe layer
TEST 33 : SIGE ON INSULATOR STRAINED AND THICKNESS MEASUREMENT
A/W
SiGe dispersion is modified by alloy stoichiometry: the ellipsometer and / or reflectometer tool can allow to build a model providing as a fit output the following parameters: ○ Relaxed SiGe thickness, target < 1 μm ○ Germanium concentration = 10 %<target< 30 %
Test wafers 14 (300 mm) shall be used for this test.

OPTION 1 : OCD AND COMPUTING ENVIRONNEMENT

The scatterometrical (OCD) morphological measurements and associated modeling of more complex structures, in a two- or a three-dimensional way is to be proposed in the options
Creating and editing offline recipes with modelling computational capability and HPC capacity is required for this option.

OCD AND COMPUTING ENVIRONMENT	
D	TEST 34 : STRUCTURE MEASUREMENTS FOR SCATTEROMETRICAL MODELIZATION
C	A/W
S	- Scatterometry CD (SE+SR): - Etch Si fields of lines (wafer 101): one line of 9 dies, variable CD - STI level, ZACT1 and ZACT2 structures (same stack, different period $50 \times 50 \mu\text{m}^2$): 36 dies - Etch gate level, ZGAT structures ($50 \times 50 \mu\text{m}^2$): 36 dies The measurement files are used for solving morphological models.
P	Results are compared to results obtained with CEA-LETI reference tool.
D	TEST 35 : MEASUREMENT RECIPE CENTRALIZATION AND DISTRIBUTION
C	A/W
S	Ellipsometry/Reflectometry/OCD: The capabilities of the server or part of it allows the storage and the distribution of the measurement recipes. Wafer maps of CEA-LETI's products and associated solving models (1D simple models or precomputed solution libraries for 2/3D OCD) and possible other parts, are combined on the server. The obtained measurement recipes are pushed from the server to the tool side or are selected from the tool in the server side. Local copy of recipe on the tool are possible in case of the server is unavailable. The software versions between server and the tool are 100% compatible (no recipe modification on the tool is requested but for recipe created on the tool, it can be transferred on the server). Current directory tree structure used in production will be replicated on the server. The server is physically located in a CEA-LETI building and connected to tools through local network.
P	Existing, or new measurement recipe from the previous sections, will be used to demonstrate the distribution and storage validity of measurement recipes on the server.
D	TEST 36 : STORAGE CAPABILITIES FOR MODEL CROSS-SOLVING
C	A/W
S	Ellipsometry/Reflectometry/OCD: The capabilities of the server or part of it allows the storage of previous measurement (raw data and associated results of model solving). These results are used for parallel solving or serial solving of synchronous or subsequent measurement.
P	The test will be performed with data collected from the wafer ref. #2 from Erreur ! Source du renvoi introuvable. The two structures ZACT1 and ZACT2 are measured at the same process level (≥ 34 points). Solving are first made separately for both structures. Common parameters between structures are injected from one to another are results are compared. A more sensitive structures can be used, according to sample availability on CEA-LETI side. The server is physically located in a CEA-LETI building and connected to tools through local network.
D	TEST 37 : STRUCTURE MEASUREMENTS FOR SCATTEROMETRICAL MODELIZATION
C	A/W
S	- Scatterometry CD (SE+SR): - Etch Si fields of lines (wafer 101): one line of 9 dies, variable CD - STI level, ZACT1 and ZACT2 structures (same stack, different period $50 \times 50 \mu\text{m}^2$): 36 dies - Etch gate level, ZGAT structures ($50 \times 50 \mu\text{m}^2$): 36 dies The measurement files are used for solving morphological models.
P	Results are compared to results obtained with CEA-LETI reference tool.

D	TEST 38 : HIGH COMPUTATIONNAL CAPABILITIES FOR OCD MORPHOLOGICAL MODELS
C	A/W
S	• Ellipsometry/Reflectometry/OCD: A dedicated offline workstation is used for creation and edition of the several kinds of model (1D, 2D or 3D). A computational capability HPC like is used to create and compute libraries of solutions for complex structure modeling. These libraries are part of the measurement recipe.
P	Results are compared to results obtained with CEA-LETI reference tool. The high computational capacity is physically located in a CEA-LETI building and connected to tools through local network.

3 EQUIPMENT TECHNICAL SPECIFICATIONS

3.1 Equipment description

3.1.1 Software capabilities

The software shall include at least the following capabilities:

1. Tool control : robot, sample control, scan control, recipe creation, data analysis
2. Manual measurement and displacement
3. Several login accesses : manager, engineer, operator, with corresponding operating capabilities
4. Management of data collection dedicated to the Statistical Process Control of the equipment
5. Management of the measurements : MS Office readable file(s) for the different analysis and the statistical data
6. Recipes and data saving : file management
7. The export of reflectance and ellipsometry spectrum to MS Excel-compatible files (.txt or .csv or xls files) must be straightforward. In addition, batch export of reflectance and ellipsometry spectra for multi-points and/or multi-wafers should be available and, if possible, user-friendly.
8. Accurate management of reflectance and/or ellipsometric raw data must be possible with both WVASE32 and Complete Ease Woollam software. Any instrumental function and/or data correction or post treatment must be detailed and provided by the supplier, so as to be taken into account in the above-listed Woollam software.
9. 1D, 2D and 3D graphic representations of the results
10. Map to map
11. Pattern recognition
12. Database management (recipes, results) with folders/subfolders architecture
13. As the tool shall include a mapping capability, the software shall allow the operator to define easily :
 - One measurement point ((X,Y) or (R,θ) coordinate)
 - Polar maps, Square maps, Lines
 - Any pattern based on imported Excel or txt file.
14. Any problem encountered during the measurement shall be listed in a txt file. Should a measurement be impossible, a comment window shall make it clear for the user.

3.1.2 Off-line software for PC (offline workstation) shall be provided : 10 licenses requested. This off-line software shall include at least the following modules:

1. Recipe creation (wafer map and stack or pattern modeling)
Data analysis: In terms of data analysis, at-line and off-line software shall include at least the following capabilities:
2. Dispersion models available :
 - Jellison, Cauchy, Sellmeier, Effective medium approximation (EMA), Oscillators, Lorentz, Gaussian, Tauc-Lorentz, Cody-Lorentz, Interpolation models (composition of an Alloy based on known composition reference samples)
3. Surface or interfacial roughness
4. Index grading
5. Point by point inversion
6. Anisotropy measurement (uniaxial and biaxial anisotropic materials)
7. Mean-Square Error estimation
8. Correlation matrix and evaluation of the uniqueness of the proposed solution
9. Multi-sample treatment
10. Display: (n,k) or (cosΔ,tanΨ) or (ε',ε'') versus wavelength (nm or μm) or energy (eV)
11. Full Mueller matrix

For complex modeling, the workstations as to be connected to computational resources

3.1.3 Software interoperability

1. The equipment software should provide ways of transferring programs and data to other clean room automated spectroscopic ellipsometer and reflectometer.
2. Nice to have tools software which can allow the automatic generation of a recipe whose mapping is given by fab host, and may differ from one plate to another.

3.2 Hardware

3.2.1 Pumping system

NA

The Contractor shall draft his recommendations for pumping according to the specifications indicated by the CEA-LETI and his own specifications.

3.2.2 Gas/chemical lines

The machine shall be equipped with the gas/chemical lines necessary for the processes and for the required performances. Each line shall be equipped with a filter compatible with the corresponding active gas/chemistry. Each gas/chemical line shall be clearly identified and equipped with a manual shutdown valve up-line from the flowmeter (line isolation).

Each gas line (or chemical line) shall be equipped with a digital flowmeter, and the information of instant flow as well as total gas / chemical volume shall be reported to the facilities. Alternatively, the information of the valve status will be reported to the facilities in order to calculate the total gas or chemical consumption.

Each gas or chemical line shall be identifiable on the control monitor of the machine, the name of the line shall indicate the name of the gas/chemistry used.

The gas/chemistry panel and the lines internal to the machine shall be manufactured and assembled using welded pipe (orbital type welding) or pipes assembled by "VCR" type joint techniques. The stainless steel used for the piping, bellows, and other parts shall be electro-polished ANSI316L steel (0.25 μm Ra).

It must not be possible for mass-flow bypasses to be in open position if the equipment is in "gas demand" (gas input valve open), so as to prevent any excessive discharge flow incompatible with the extraction systems (example: dilution by a neutral gas for flammable gases).

3.2.3 Equipment consumption monitoring

All fluids that are controlled in flowrate through Mass Flow Controllers shall be monitored by equipment software and their consumptions shall be recorded. This shall include at least process gases, chemicals and de-ionized water. Fluid consumption data shall be accessible on equipment user interface for viewing and shall be readily exportable to cleanroom IT network through SECS/GEM protocol in dedicated SVIDs.

3.2.4 Idle mode management and interface with peripheral sub-equipments

The equipment shall be able to detect idle time and trigger relevant actions aimed at decreasing power and fluid consumptions (for instance: temperature decrease, purge flowrate decrease...). Idle time threshold to trigger these actions shall be setttable through equipment user interface. Upon restart all equipment process parameters setpoints shall be automatically restored and process launch shall be inhibited until parameters have reached their setpoints.

The equipment shall embed an interface box to manage communication with peripheral sub-equipments (pumps, abatement systems...). Communication with sub-equipments shall rely either on dry contacts or on Ethernet connection. The interface module shall be able to collect information from sub-equipments (status, alarms, warnings) and trigger relevant actions on the equipment (process aborts, process inhibits...). Such actions shall be setttable on equipment user interface. The interface module shall also be able to send standby commands to sub-equipments in order to decrease their power and fluid consumptions during idle times, which commands shall also be setttable on equipment user interface (pump speed decrease, abatement burner shutdown...). Upon restart nominal sub-equipment operation shall be automatically restored and process launch shall be inhibited until nominal operation level of all sub-equipments is reached.

3.2.5 Flammable gas management

The flammable gases, particularly pure or mixed silane and hydrogen, will be diluted by pump ballast nitrogen at vacuum pump outlet, so that the concentration is $< LIE (LEL) / 2$. Ballast flowrate shall be monitored by the equipment and flammable gas dispensing shall be inhibited if it is below dilution requirement. Required nitrogen flowrate will be calculated based on the maximum flowrate that can be delivered by the MFC.

3.2.6 Temperature control

NA

Heat exchangers / Chillers

The Contractor shall price the heat exchangers and chillers as an optional item.

The Contractor shall draft his recommendations for heat exchangers and chillers according to the specifications indicated by the CEA-LETI and his own specifications.

3.2.7 Vibrations

The Contractor will provide the vibration emissivity specifications (amplitude and frequency) of the equipment and its sub-elements.

The Contractor will provide the vibration sensitivity specifications (amplitude and frequency) of the equipment and its sub-components.

3.2.8 Other

NA

3.3 Software

3.3.1 OT configuration

The supplier must provide us with a dedicated IT specialist contact.

Software Update and Upgrade

The Contractor shall systematically provide CEA-LETI with updates (bug corrections, etc.), upgrades, and the latest version of the software as soon as it becomes available and shall install them free of charge during the warranty period.

After the warranty has expired, the Contractor will keep CEA-LETI informed of any upgrades or new versions that improve functionality and provide pricing conditions if requested by CEA-LETI.

Notwithstanding the warranty expiration, the Contractor will perform the software modifications needed to fix any bugs and thus maintain the original functionality of the software at no cost to CEA-LETI. Modifications related to corrections (bugs, etc.) shall be supplied and installed free of charge.

Through-the-Wall Installation

If the equipment is installed in through-the-wall mode, user interface stations shall be available in both white and grey areas. The two control stations shall not be active at the same time.

3.3.1.1 Full OT Description of the Equipment

In the context of connecting to the cleanroom information system, the equipment supplier must provide us with:

- Number of PCs and controllers in the network within the equipment
- System configuration of each pcs
 - Operating system
 - Processor(s)
 - RAM
 - Hard drives capacities

- MAC address
 - Network diagram of the different PCs, with the connection to the cleanroom information system highlighted.
- Presence of remote PCs/stations with a list of ports and communication protocols between the station and the equipment
- Presence of servers or computing stations associated with the equipment:
 - Provide a list of ports and communication protocols between the station and the equipment
 - Installation recommendations
- Presence of internal storage type NAS.
- In general, the list of protocols and ports required on the industrial network

3.3.1.2 Time Server (NTP)

To ensure proper timestamping and consistency of the different results and processes of the equipment, the supplier will provide the procedure to configure an NTP server.

To avoid any malfunctions, all PCs of the equipment must be synchronized with this server.

3.3.1.3 Naming of Workstations and Other Requests

To ensure proper tracking of the equipment, is it allow to modify the name of the PC(s) connected to the network? CEA-LETI recommends the presence of the supplier on the day of network connection.

3.3.1.4 Remote access

Remote access can be set up.

This requires the ability to install a VNC server (UltraVNC) or SSH (for Linux) on the PC connected to the information system.

The supplier will have the ability to connect to the equipment via a web proxy and access the keyboard, mouse, and screen of the PC under the supervision of the equipment manager.

File transfers are prohibited via remote access.

For data transfer needs (log uploads, downloading updates, etc.), other solutions will be available but will be studied on a case-by-case basis depending on the sensitivity of the equipment data.

Remote access will be occasional and used solely to facilitate maintenance and qualification issues of the equipment but never for remote operation.

3.3.2 Antivirus and Data Backup

CEA-LETI performs backup copies of all data stored on all computers and associated peripheral devices of the equipment.

This is achieved by performing both:

- A complete capture of all disks, with a tool like "Symantec Ghost" or Clonezilla
- An automatic data copy, capturing (on a periodic basis) updates to recipes and parameters of the equipment during operation

3.3.2.1 Backup Procedures (Full Images) of Hard Drives

CEA-LETI uses Clonezilla to create full images of all PCs in the equipment.

If the supplier does not allow CEA-LETI to use Clonezilla,

the supplier must provide a procedure and all necessary equipment for backups and restorations of the different PCs.

They will train CEA-LETI maintenance staff in the correct application of this procedure.

A backup will be performed for the acceptance of the tool and equipment.

The frequency of these backups will be defined with the equipment manager and the supplier (monthly, annually, etc.).

If the software has a protection mechanism that could interfere with the replacement of the equipment disk, then the supplier must provide CEA-LETI with the method to reactivate the software. This is particularly mandatory if a new user license key is required by the software after a hard drive change.

3.3.2.2 Backup of Recipes and Parameters

The supplier must provide a procedure to back up and restore the recipes and parameters of the equipment. This backup will be stored on the network.

3.3.2.3 Antivirus

Mandatory for All Windows PCs of the Equipment Connected to the Information System.

CEA-LETI proposes four antivirus solutions:

- Symantec SEP
- TrendMicro Apex One
- TRELLIX:
 - Application control: sealing based on a whitelist without active scanning.
 - Endpoint security: antivirus with active scanning

For antivirus solutions with active scanning:

- An exclusion list can be set up to avoid disrupting the business software. The list must be provided by the supplier.
- There is no complete scan of PCs during production.

3.3.3 Automation

Contractor shall provide the CEA-LETI with:

- The software and licenses required to operate the SECS / GEM interface
- The peripheral hardware required for the SECS / GEM interface (ex: network interface, etc.)
- Documentation (in English) associated with the SECS / GEM interface

The equipment shall implement the following mandatory standards:

- SEMI E5 (SECS-II)
- SEMI E30 (Generic Equipment Model)
- SEMI E37 (HSMS)
- SEMI E37.1 (HSMS-SS)
- SEMI E37.2 (HSMS-GS)
- SEMI E39 (Object Services)
- SEMI E40 (Process Job Management)
- SEMI E84 (Carrier Handoff Parallel IO Interface)
- SEMI E87 (Carrier Management)
- SEMI E90 (Substrate Tracking)
- SEMI E94 (Control Job Management)

The equipment shall implement the following optional standards:

- SEMI E41 (Exception Management)
- SEMI E42 (Recipe Management)
- SEMI E53 (Event Reporting)
- SEMI E54 (Sensor/Actuator Network)
- SEMI E58 (Availability, Reliability, Maintainability)

- SEMI E95 (Human Interface)
- SEMI E98 (Object Base Equipment Model)
- SEMI E99 (Carrier ID Reader/Writer)
- SEMI E109 (Reticle and Pod Management)
- SEMI E116 (Equipment Performance Tracking)
- SEMI E120 (Common Equipment Model)
- SEMI E125 (Equipment Self Description)
- SEMI E126 (Equipment Quality Information Parameters)
- SEMI E128 (XML Message Structure)
- SEMI E132 (Client Authentication and Authorization)
- SEMI E134 (Data Collection Management)
- SEMI E138 (XML Semiconductor Common Components)
- SEMI E139 (Recipe and Parameter Management)

The Contractor must complete and deliver to CEA-LETI **Appendix J** « SECS/GEM Compliance »

It should be noted that, during the equipment acceptance, a total of 5 working days will be needed for automation tests. During these 5 days, the support of a field support engineer will be required on site. A software automation engineer should also be available for remote support (mail, online conference, phone, etc...)

3.4 Transfer and handling of wafers

This section deals with the relationship between machine, wafer carriers and wafers.

3.4.1 Wafers specifications

Wafer characteristics	Specifications
Diameter	300 mm & 200 mm
Material	Silicon, glass, SiC, Saphir, GaN, III-V
Thickness of the substrate	Ability to handle various substrates with thickness in the 350 µm –1.450 mm range. For instance, the typical thickness ranges of usual substrates are: • Standard wafer (between 700 and 800 µm) • Thin wafer (between 350 µm to 500 µm) • Si (111) substrate (1000 and 1100 µm) • SiC with different resistivity (350 to 500 µm) • Glass substrate: between 350 and 900 µm
Bow and warp	< 500 µm

3.4.2 Load ports

300mm

Load ports must be compliant with SEMI standards referenced in appendix G.

INFOPAD configuration:

INFOPAD settings shall be configurable in order to meet CEA-LETI requirements. CEA-LETI uses different INFOPAD configurations based on wafers metallic contamination grade (FEOL, BEOL, packaging) to prevent processing on improper equipment. Loading of a FOUP with INFOPAD configuration not matching the equipment contamination level shall inhibit process launch and generate relevant alarms. INFOPAD configuration details corresponding to equipment metal contamination category will be given during installation and proper operation with respect to CEA-LETI rules shall be verified as part of acceptance tests.

200mm

Open cassette load port will be covered with a safety standards compliant interlock system. Any transfer will be prohibited if the sas door is open.

Document title : Automated Ellipsometry-Reflectometry tool for 300 and 200 mm wafers

N° Chrono : DRT-LETI-DPFT-SMCP-LPMS-25-10-002363

Safety mechanism must be compliant with "Machinery" directive 2006/42/EC. See Appendix D: Specifications for delivering work equipment (Compliance with European machinery directive 2006/42/EC).

BRIDGE tools 200-300 :

The 200 mm open cassette load port will be preferred.

If not, the equipment must be able to accept by preference order the following inserts: AM 3004-2, AM 3004-3, AM3005 or AM 3000. In this case, an equipment compatible insert shall be delivered.

3.4.3 Handling and contact surfaces

NA

3.4.4 References of wafer carriers used on equipment

FOUP 300 mm :

- F300 Autopod Wafercarrier- color = red (ENTEGRIS)
- SF 300. 02 Version V- color = yellow (DAINISHI)
- Spectra S - color = red (ENTEGRIS)

Carrier 200 mm :

- DMS Wafer Carrier 8" black antistatic TYP A5 n°780-550000005

3.4.5 Handling system reliability

The handling system reliability will be checked through a "marathon test" using both type of wafer : bare silicon <100> and SiC wafers.

During Pre-Acceptance :

15. one overnight run with 200 mm wafers of SiC
16. one overnight run with 300 mm wafers of Si

During Acceptance :

17. Three overnight runs with 200 mm wafers of SiC
18. Three overnight runs with 300 mm wafers of Si

All the loading stations, loadlocks, buffers, process modules or chambers will be checked.

No wafer rubbing.

No move potentially inducing particle on the wafers.

3.5 Mini environment

This section is only relevant for equipments operating, at least partly, under atmospheric pressure.

Parameters	Specification
Overpressure of the mini-environment with respect to the clean room	> 1 Pa
Blowing speed at 10 cm under filters	Between 30 and 40 cm/s
Blowing speed at the level of the wafers	Between 20 and 40 cm/s
Integrity of filters	Visual check

3.5.1 Check of the physical characteristic of the air

In no event shall any necessary slight overpressure of the environmental chamber compared with the room affect to the confinement with odors nor cause a risk of spreading aerosols nor other vapors in the operator environment. During in situ tests, the Contractor shall be responsible for adjusting air speed of fan filter units (FFUs).

The service includes all equipment, auxiliary modules (air conditioning units (ACUs), fans, and filter housing) and systems necessary for maintaining temperature and humidity conditions and controlling particulate contamination (and molecular if necessary) in the equipment.

3.5.2 ESD (Electrostatic Discharge)

The equipment must be made of dissipative materials in particular, in so-called sensitive areas (< 25 cm from devices):

- Carrier loading/unloading plates,

- Plant unit transfer arm/shovel,
- Chuck/support plates.
- Casing.

For surfaces located at less than 25 cm from the wafers, the electrostatic discharge must be less than 100 V/inch (circuit breakdown voltage).

If the machine is equipped with ionising bars:

Measurements of ionising bar efficiency at the level of the plates	• Time of the positive discharge from + 1000V to + 100V < 20s • Time of negative discharge from – 1000V to –100V < 20s
Contamination check on the tips of ionising bars	• Whitish deposit (to be cleaned)

3.5.3 Particle checks

This section refers to particle counts in air flowing through the mini-environment.

Particle check in static mode

The sampling probe of the particle counter is placed at the location representing passage of the plates.

The mini-environment will be checked at 7 sampling points with a sampling time of 1 minute per point.

The maximum number of particles allowed will be 35 particles per m³ of size > 0.1µm (or 1 particle per ft³)

Particle check in dynamic mode

The probe is placed close to the various moving elements.

Specific attention will be paid to parts which may present friction.

The mini-environment will be checked at one sampling point per site in motion with a sampling time of 1 minute per point.

The maximum number of particles allowed will be 3,500 particles per m³ of size > 0.1µm (or 100 particle per ft³)

3.6 Interface with the rest of the clean room and its organisation.

The equipment must be compatible with the environment for which it is intended.

It should not degrade the environmental conditions of the room according to the following constraints (see the environmental conditions in Annex B):

- The cleanliness class (It should respect the cleanliness class according to ISO 14-644-1)
- Temperature
- The relative humidity
- The VOC (Volatile organic compounds) content: VOC <50ppb
- The air contamination (Any parts likely to release particles or other contaminants should have an appropriate extraction)

The Contractor should respect ISO 3 to ISO 8 clean concept rules.

The provider must follow the rules of "clean concept" imposed in accordance with quality documents mentioned in this specification.

Regarding the personnel involved in clean rooms, the service provider provides the CEA-LETI with a proof of a registered training in "Clean environment concept in micro and nanotechnology" for both himself and his possible subcontractors.

3.7 Contamination

3.7.1 Particle contamination

Following particle contamination specifications shall be achieved by the equipment and equipment performances shall be verified as part of acceptance tests. Equipment shall also consistently achieve these performances over the course of the warranty, which will be verified through tests carried out by CEA-LETI on a regular basis.

Test #	Test name	Method	Result to pass
C1	Frontside particle contamination: handling	Silicon monitors Handling (mechanical only) in and out of process chambers Pre and post-handling particle measurements with unpatterned wafer defect inspection system	<300 particles @ 70nm minimum particle size 3 consecutive wafers within specification
C2	Frontside particle contamination: process	Silicon monitors Representative process to be agreed upon between CEA-LETI and Contractor Pre and post-process particle measurements with unpatterned wafer defect inspection system	<300 particles @ 70nm minimum particle size 3 consecutive wafers within specification
C3	Backside surface condition	Silicon monitors Handling (mechanical only) in and out of process chambers Backside measurements with unpatterned wafer defect inspection system NB: for 200mm equipments, wafers will be handled upside down (polished side in contact with robots, chucks etc...)	No scratch signature on defect map 3 consecutive wafers within specification No result drift: total defect count for backside measurement of wafer ID #3 must not exceed total defect count for backside measurement of wafer ID #1 by more than 10%

3.7.2 Metallic contamination

The metal contamination specifications are those that the equipment must have when it enters the cleanroom.

This control is a handling test. It reports on the level of metal contamination at the end of installation, before the equipment acceptance tests are started and before any process tests.

The test wafers must be handled throughout all the equipment modules.

The process acceptance tests are mentioned in section 2 of the specifications document.

Test C4 : Use Monitor quality silicon substrates.

Loading/unloading (handling) in **all equipment modules**.

Test C5 : Use Monitor quality silicon substrates

Loading/unloading (handling) in **all equipment modules**

NB: For equipment handling wafers with a diameter of 200mm or less, the wafers will be handled upside down (polished side in contact with robots, chucks, etc.).

Test #	Test name	Analysis method	Result to be achieved
C4	Metal contamination Front side	TXRF measurement analysis with mapping	For all the elements measured ⁽¹⁾ : Average: < 1 ^{E11} at/cm ² Localised peak: < 1 ^{E12} at/cm ²
C5	Metal contamination Back side	TXRF measurement analysis with mapping	For all the elements measured ⁽¹⁾ : Average: < 1 ^{E11} at/cm ² Localised peak: < 1 ^{E12} at/cm ²

⁽¹⁾ List of elements measured in TXRF : Na, Mg, Al K, Ca, Ti, Cr, Fe, V, Mn, Co, Ni, Cu, Zn, Ga, Ge, As, Sr, Y, Zr, Nb, Mo, Ru, Pd, Ag, Cd, In, Sn, Sb, Te, Ba, La, Hf, Ta, W, Ir, Pt, Au, Pb, Ce, Gd, Dy, Er, Yb, (this list of elements may be modified at the discretion of LETI)

⁽²⁾ List of elements « CONTA 1 » : Al, As, B, Ca, Co, Cr, Cu, Fe, Ga, Ge, Hf, K, In, Li, Mg, Mn, Mo, Na, Nb, Ni, P, Pb, Sb, Sn, Ta, Te, Ti, V, W, Y, Zn, Zr, (list of elements which may be modified at the discretion of LETI)

4 GENERAL BUILDING, FLUIDS, ELECTRICITY, ENVIRONMENT SPECIFICATIONS

4.1 Environment of the equipment

4.1.1 Building specifications

Features of the location of the equipment:

- Environment: [cleanroom](#),
- Cleanliness class according to **ISO 14-644-1**:
 - **52B**: **ISO 4-6** depending on the installation site in the building
- Environmental Conditions and tolerances (temperature and humidity)
 - **52B**: **21 +/- 2 ° C // 47 +/- 5% RH** except for the 2 following areas:
- Mounting: Password walls or openspace
- Location of devices: basement, gray fingers

The Contractor must ensure that the Equipment installed in a clean room will not have to disturb modify the characteristics of the zone.

In case a furnace needs to be installed in our facilities, the Contractor must provide the equivalent thermal power.

4.1.2 Building fluids

In the case of fluids (liquids or gases), the Contractor must ensure the compatibility of its equipment with CEA supply sources.

Examples: chemical drums, gas cylinder sizes, etc.

See **Appendix B**: General fluids building [52B](#)

4.1.3 Building power network specifications

CAUTION:

The equipment covered by these specifications must be connected to an electrical distribution mains with earthed neutral system (TN –S diagram).

If necessary, refer to CEI 60364 standard

Electrical features

Power supply voltages available on main:

- Single-phase: 1 phase + neutral + earth
Phase/Neutral voltage: 230 V +/- 10 %
 - Three-phase: 3 phases + neutral + earth
Phase/Phase voltage = 400 V +/- 10 %;
Phase/Neutral voltage = 230 V +/- 10 %
- Main frequency: 50 Hz

4.1.4 Adaptation of the machine to the power network

CAUTION:

When the neutral lead is distributed in the machine, a cut-off device must be placed on the neutral lead, at the equipment item's general switch.

Neutral lead colour in machine:

Inside the equipment, the neutral lead shall be of light blue colour (EN 60204 standard) or clearly identified otherwise (colour ring, marker).

Protection lead colour in machine:

Inside the equipment, the protection lead (earth) shall be of green and yellow colour.

Power supply transformer (general machine)

Should a transformer be necessary :

- Contractor shall estimate this supply as an option, indicating all electrical features (power, primary and secondary voltages, etc.).
- A dry transformer (without liquid dielectric medium) is preferable;
For transformers or other devices, containing a liquid dielectric medium:
 - Pyralene is prohibited;
 - Installation conditions in machine shall meet Decree of January 17, 1989 establishing prevention steps against fire hazard introduced by dispersion and ignition of flammable liquid dielectric media. In this case, mandatorily consult us.
- Characteristics of the transformer:
 - It shall be compliant with the "low voltage" directive **2014/35/EC** and affixed with the CE marking for this purpose,
 - case of a three-phase transformer:
Secondary windings must be bridge connection so that there is a neutral point
This provision applies even if the neutral is not used by the machine in order to enable protection against indirect contacts (ground connection if necessary)
- For "dry" transformers, the applicable construction standards are:
 - **NF EN 61558** standard, for powers of less than 25 KVA single-phase, or 40 KVA three-phase
 - **NF EN 60076** standard, for powers in excess of 25 KVA single-phase and 40 KVA three-phase

4.1.5 Uninterruptible power supply (UPS)

Should all the equipment be powered by an emergency power supply (UPS), this power supply shall be provided by CEA.

Contractor shall provide all the necessary information for defining the product (voltage, power, autonomy).

Contractor shall provide lock terminals on the equipment to connect the emergency power supply.

If only a section of the equipment is powered by an internal UPS incorporated by the manufacturer (IT section for example), the following rules shall be complied with:

- An omnipolar separation mechanism shall be installed downstream of the UPS in order to allow maintenance operations.
- The presence of voltage after shutoff of the machine master switch shall be signalled on same.
- The circuits still powered after cut-off must be identified in orange inside the equipment as per standard **NF EN 60204**.

4.2 Management of the environment

In reference to its “Sustainable Development” initiative, CEA-LETI is working on improving its environmental performance and would like understand what its service providers and Contractors' contributions are to this regard.

Contractor shall therefore list in its offer all the initiatives that it has undertaken and / or is planning to undertake to make its business more sustainable from an environmental and social perspective. It will provide details about:

- its efforts regarding reduction in :
 - consumption of electrical and heat energy, and fluids ;
 - exhaust flows through careful design of covers and exhaust points ;
 - cooling water flow rates using an optimized calculation for heat exchangers.
- proposed fluid recycling.

The equipment must be designed so as to limit polluting emissions in the environment in particular by implementing clean technologies, segregation and treatment of effluents and waste depending on their characteristics, and reduction of the discharged quantities.

The Contractor will provide emissions evaluation:

- vapour/gaz emissions rate and liquid chemical wastes
- Actives wastes mass and volume of if possible, pollutants rate in rinsing wastes.

4.2.1 Process Cooling Water

Contractor will provide design calculations for heat exchangers to be connected to the buildings process cooling water supply system (allow for delta T of at least 5°C). If necessary, it will also justify pressure relief valves on the valve console. In the event flexible pipes are used in the equipment or for links with auxiliary modules, connections using a single Swagelock rubber series PB from-end or the equivalent with a central tube in Buna N, braided-fiber reinforcement and covered with abrasion-resistant, nonflammable Buta N. End-pieces will be the push-on type and/or double-ring in 316 stainless steel adapted for the required pressure (Serflex or similar collars are prohibited). Color of flexible piping: blue for “inlet” into the equipment and red for “outlet”.

4.2.2 Exhaust and other internal equipment air systems

The Contractor will provide design reports or tests used to define air flow rate required to comply with current regulations. It will select the sections of adapted systems in order to limit resistance (air speed < 8m/s for exhaust and < 6m/s for supply). It will study optimal routing inside the equipment, particularly by limiting the number of specific head losses. If flexible piping is used, they shall be classified M1 for fire and be of the smooth interior type adapted to the fluid being carried.

Drawings will be provided before construction to indicate routing of air systems (exhaust and supply), design inside the equipment and its auxiliary modules.

In the case of extracting calories from power box cabinets or electrical bays located in the clean room, an extraction fan must be integrated into the cabinet or electrical bay: the “hot air flow” will be extracted from the cabinets or electrical bay and it will be redirected directly into the false floor of the clean room.

4.2.3 Segregation of liquid effluents

Depending on their composition, liquid effluents shall be directed to dedicated drains.

Fluorinated effluents whose concentration is more than or equal to 1% fluoride, as well as phosphorus effluents must be directed to the drain for fluorinated / Phosphorus effluents. Temperature shall not exceed 50°C

Solvent effluents must be directed towards the solvents drain.

If the process involves using heavy metals (copper, nickel, gold, cadmium, etc.), a specific collection drain as well as interfacing with the dedicated recovery system for these effluents shall be provided for by Contractor. The HSE cell shall validate the collection and treatment mode for these effluents.

The means for transporting dangerous or unsanitary fluids and for the collection of effluents which are polluted or are likely to be so are sealed and resist the physical and chemical action of products which they are likely to contain.

4.2.4 Case of DI return or recycling of ultrapure water

Contractor will provide DI flow evaluation (for mainframe and all sub-systems):

- process flow
- idle flow

Reclaim drains collecting non-polluted ultrapure waters used for maintaining the quality of equipment is available in building 4102 and BHT, in an initiative for rationalising and saving processed water.

Where possible, Contractor shall provide for a "DI return" outlet collecting all the water used to preserve the quality of the equipment, guaranteed without contact with the process chemicals (recirculation loop, recirculated bath, etc.). This 'DI Return' outlet shall be equipped with an adjustable flow meter. The Contractor will provide data showing the minimum necessary water flow to keep the process / equipment quality.

In the case of wet bench or similar equipment using ultra-pure water, the quality of water is maintained through a programmable flush rather than permanent leak flow.

Moreover, in the case of rinsing containers or equivalent process, it will propose the possibility of recovering rinsing water excluding raw sewage for a collection in a "reclaim" drain and reuse of this water in the facilities water.

4.2.5 Gaseous effluents

Depending on the process and the operation mode of the equipment, the installation of a gaseous effluents treatment system will be decided by CEA-LETI.

Contractor shall provide the information required for the needed analysis: gas quantities of the standard process recipe, sub-products of the reaction, etc.

The Contractor must be pro-active regarding the nature and conditions for setting up a reduction system which is compatible with its equipment.

CEA-LETI reserves the right to refuse the proposal of the abatement system recommended by Contractor.

4.2.6 Odours

The required steps must be taken in order to limit odours from effluent processing. The Contractor will carry out the studies and the design of its equipment for an effective capture at source of aerosols, chemical vapors and other gas effluents to ensure the personnel 'safety against the risk of inhalation and the protection of the process in the environment of the equipment. Before delivering the equipment, it will perform factory testing to demonstrate that the level of risk is acceptable and provide associated reports. In the event of failing extraction, he will do the necessary modifications until obtaining the requested results.

All the equipment will be equipped with covers adapted to the activity. These protections will have to allow reduction of the air flows to put in place for rationalizing energy and better efficiency without bringing ergonomic constraints which can endanger the operator.

The Contractor will integrate in the design of its equipment protections and other points of catchment considered necessary at the time as of maintenance operations.

5 SAFETY

5.1 EC conformity

The supplied equipment or service shall meet the regulations in force in France.
Said regulations include the European directives transposed into French Law.

European Directives:

Compliance with the European directives applicable to the equipment is mandatory.

In particular (if applicable) :

- “Machinery” directive **2006/42/EC**
See **Appendix D**: Specifications for delivering work equipment (Compliance with European machinery directive **2006/42/EC**).
- “Electromagnetic compatibility EMC” directive **2014/30/EU**
- “Low voltage” directive **2014/35/EU**
- “ATEX” directive **2014/34/EU**
- “Pressure” directive **2014/68/EU**

The equipment shall be EC certified, a “CE marking” shall be affixed thereon and it shall be accompanied by an EC/EU declaration of conformity.

Construction standards

Compliance with harmonized European Standards (NF EN or NF EN ISO) will be favored, the application of these standards giving a presumption of conformity on the subjects concerned.

- **Risk analysis**
The various risks (mechanical, electrical, thermal, gas, chemical, radiation) shall be clearly mentioned by Contractor in its proposal.
The risk analysis will be made according to the applicable reference standard: **NF EN ISO 12100** : "Safety of machinery - General principles of design - Risk assessment and risk reduction"

These risks shall be handled :
 - in accordance with the instructions of the applicable directives:
 - in accordance with the recommendations of Paragraphs 5.2 to 5.12
- **Design of safety related parts :**
The safety functions will be designed in accordance with standard **NF EN ISO 13849-1 "Safety of machinery - Safety-related parts of control systems - Part 1: general principles of design" for each type of hazard (mechanical / gas / thermal...)**
- **Electrical equipment of machines**
The electrical equipment of machines will be designed in accordance with standard **NF EN 60204**

Reminder of technical points in relation with the regulations:

Warning :

This paragraph is aimed at attracting the manufacturers' attention to a few specific technical points which may lead to non compliance if they're not completed.

- **Energy separation device**

The equipment will be fitted with an isolation device on each energy source (electricity, pneumatic, nitrogen, etc.) that can be locked in the off position.

- **Electrical cabinets**

Electrical cabinets will have an IP2X protection index and it will only be possible to open them with a tool or a key ; the inside of the cabinet will also have an IP2X protection rating so as to avoid any risk of direct contact during maintenance operations (components / wiring)

- **Guards design**

- Protection panels:

Protection panels (guards) will be strictly designed in compliance with Machinery Directive **2006/42/EC** (See appendix F: 1.3.8 to 1.4.3)

Moreover, the following conditions shall be complied with for selecting guards:

Fixed guards:

The installation of fixed guards by manufacturer will be accepted if:

- Frequent disassembly for maintenance is not necessary
- Removal of guard is exclusively reserved to maintenance personnel by following a written instruction drawn up by manufacturer (lock out tag out of affected moving elements for example).

Moving guards:

Moving guards will be considered as all types of guards installed on hinges (doors) or not complying with the criteria of fixed guards.

- The opening of the movable protectors will have to stop the risks present behind these protectors, by means of a safety system designed in accordance with the applicable European standards.
 - The opening detectors installed on movable guards will be safety components in accordance with **NF EN ISO14119**

- **Maintenance modes**

If the machinery is equipped with "maintenance" or "service" mode in which the safety systems are neutralised, these modes will be strictly designed in compliance with Directive 2006/42/EC "Selection of control or operating modes"

(See: appendix F point 1.2.5)

Consequently:

- The maintenance of the equipment should not require the direct neutralization of the detection components (interlock doors). If this neutralization is necessary it should be done via a maintenance mode accessible via a code or a key and simultaneously cause the reduction of risks (reduction of speeds, permanent control of the movements ...)
 - The maintained action required to validate the movements will be of the pedal type or "dead man" safety handle.
In particular, this system will be present on the control modules ("teach pendant ") for teaching robots.

- **Fume cupboards**

In case of fume cupboards, the applicable standards are:

NF EN 14175-1, NF EN 14175-2, NF EN 14175-3, NF EN 14175-4, NF EN 14175-6, NF EN 14175-7.

Factory and onsite "type tests" shall be subject to a conformance certificate or Contractor declaration. The Contractor shall anticipate all exhaust surveillance devices, associated servomechanisms and operator information devices on equipment operating state.

5.2 Risks connected with facilities

Power supply sectioning:

A power supply-sectioning device must be designed on the equipment for each energy source of the machine

Electrical supply cut-off device:

The accessories enabling the electrical supply of all or part of the machine to be immobilised shall be supplied with the equipment (locking circuit breakers in off position).

Compressed air connection or "service" nitrogen:

When the equipment uses compressed air or nitrogen for valve, actuator and other system control, the machine must be equipped with a general shut-off valve.

This valve must include a locking system, by means of a padlock, in order to make the facilities safe for maintenance. One or more drain/purge systems must be available to dissipate the residual pneumatic energy stored in the machine after general valve shutting-off. Energy dissipation must be harmless to any exposed personnel or operators.

Presence of an uninterruptible power supply (UPS):

The instructions of Paragraph 4.1.5 shall be complied with.

The cut-off component at UPS output may be locked in "off" position.

5.3 Risks connected with fire

Automatic fire extinction system for equipment using solvents:

Equipment implementing solvents in open tray (pans, most often) must have an automatic CO2 extinction system. This system will be connected to the operation of detectors (smoke, flame, temperature, etc.) installed above open trays, but also at equipment retention trays.

DESAUTEL (or equivalent) type automatic extinction systems certified and validated by qualified authorities shall be installed with approval of the facilities department. Dry contacts shall be supplied in the building in order to report each of the following elements of information:

- System disturbance
- Fire detection (1 detector giving alarm)
- Confirmed fire detection (2 detectors giving alarm, extinction triggered)

Intrinsic equipment fire detection system:

When fire detectors are supplied with the equipment, they must be accompanied by the risk analysis leading to their installation, in such a way that the LETI is able to make decisions on the grounds for doubling said detection using existing systems in the building which are compatible with the fire systems in place. Detectors integrated into equipment shall not be connected with the fire system of the building and shall only have an action on the equipment in question and its related peripheral devices, if required.

The Contractor will specify and provide the necessary documentation relating to:

- Periodic calibration of sensors: frequency, operating mode, calibration gas used, parts to change in preventive and corrective maintenance, and any information necessary to maintain the detectors in good working order.
- Connections required on the equipment, in case of:
 - Detection alarms for different thresholds
 - Malfunctions

A list of these interlocks with the corresponding wiring diagrams will be provided.

5.4 Risks connected with chemical products

- When chemical products (solid, gaseous or liquid) are supplied by the Contractor within the framework of installing equipment, testing or any other operation, it must comply with **EC regulation 1907/2006**. It must also supply the full list of products as well as safety information sheets in French for each product. These documents must comply with European directive CLP.

The CEA-LETI shall be particularly vigilant with regard to compliance with content, pictograms and classification used, as well as the provision of a version drafted in French.

- Product classified as noxious, toxic, extremely toxic, corrosive, etc. (e.g., fluorhydric acid with a concentration greater than 7%, gas, etc.) supplied by an outside source to the equipment shall be distributed with double-walled pipe up to the equipment intake. Pipes connecting dangerous chemical fluids between the equipment and auxiliary modules will also be double-walled.
- If there is a risk in a chemical containment of the equipment during a maintenance operation, a safety device in the system shall be able to cut power supply of devices that may present a risk to personnel.

All equipment containing liquid chemicals must be organised in such a way as to create a retention system aiming at preventing the accidental spread of said products outside the equipment without voluntary action. All elements of the installation in the equipment that could be a source of leaks (fittings, valves, filters, etc ...) will be placed on the retention and under extraction.

- These retention systems shall be fitted with leak detectors reporting the information to the equipment control console. Alarm enabling of a detector shall interrupt automatic supply to the machine and the chemical fluid circulation.

The detectors shall be tested before activating the equipment.

- The operation of equipment shall be connected with the proper operation of the extraction. The extraction level shall be permanently controlled by one or several extraction controllers which will drive a visual alarm per stack light (code green, orange and red) and a sound alarm on the working station and if necessary on the concerned sub equipment). These sensors will give an indication of current negative pressure level and shall also ensure equipment safety servo mechanisms in the event of an alarm. It must be possible to recalibrate the sensors on site to correct drifts over time. A calibration certificate shall be provided upon installation.

For each type of control sensor used on the exhaust a spare sensor will be delivered with the equipment to be kept as a spare part.

- NB: for automated equipment, this "extraction" alarm may be linked with the other types of alarms on the equipment control consoles.
All equipment modules and devices (reactor, chemical vat, stove, coater, gas or chemical storage cabinet including the lower cabinets of the benches, canisters, etc.) and, more generally, any compartment where a leak may occur including those housing connections, valves, pumps, etc., that present a risk to operators shall be included in the exhaust system.
- In order to ensure efficient exhaust, the mobile front should have no rim.
Ideally, the bench should have 2 exhaust strips: a first one on the worktop level and a second one located on the top of the bench, in order to promote the exhaust of chemical vapours.
If the bench includes bulky elements (ultrasonic tank, oven, etc.), these elements must be embedded in the worktop and not on the top of it in order to prevent any perturbation of exhaust and aerolics performance.
- Chemical product trays of pans must be equipped with an adjustable time delay automatic drainage system in such a way that solutions may be automatically directed towards drains in the event of a prolonged shut-down of extraction.
- For the requirements of certain processes, chemical products will need to be heated. At the end of operation, these baths may only be evacuated to designated drains if the temperature of the bath does not reach 60°C. For higher temperatures and for drainage in the "solvent" drain, a study must be conducted in order to determine the best solution: PVDF material, dilution module, thermal exchanger, etc.

If the solution selected by the Contractor consists in installing a buffer tank to enable these effluents to cool, it must be located under retention and be equipped with an adjustable time delay drainage system as stated previously.

- For equipment with processed chambers, the Contractor must provide the list of expected by-products in the event the chamber is opened, in order to facilitate maintenance operations.
- For equipment with gas detectors, The Contractor will specify and provide the necessary documentation relating to:
 - ✓ Periodic calibration of sensors: frequency, operating mode, calibration gas used, parts to change in preventive and corrective maintenance, and any information necessary to maintain the detectors in good working order.
 - ✓ Connections required on the equipment, in case of:
 - Detection alarms for different thresholds
 - Malfunctions

A list of these interlocks with the corresponding wiring diagrams will be provided.

- For solid compounds used as insulating materials in furnaces, the Contractor will provide all relevant information on the nature and dangerousness of these materials: Material Safety Data Sheet (MSDS) should be provided. If one of these materials contains Refractory Ceramic Fibres (RCF), the Contractor must provide costed alternatives: substituents and less dangerous materials than RCF.

5.5 Risks connected with handling

For the parts of equipment requiring handling: pumping units, chamber lids, covers, etc., notably during maintenance or installation operations, lifting means must be foreseen and described in the equipment safety notice.

Systems integrated into the equipment will be favoured over mobile systems.

In the case of a mobile system, it must be marked "CE", be the subject of an EC declaration of conformity and an instruction manual in French.

5.6 Risks connected with automatic loading of Foups onto LoadPorts

As part of the project to automate the loading of FOUPs onto load port using automatic loaders (MHF), the equipment will be fitted with immaterial safety bars in the load port area or any other material to address the risk of personnel being crushed by the equipment. The implementation of this safety measure complies with the European Machinery Directive 2006/42/EC.

5.7 Risks connected with pressurised equipment

For equipment subject to "Pressure" directive **2014/68/EU**, Contractor shall:

- Provide a complete file of the equipment in order to enable the commissioning inspection operations
- Update the roll where all the interventions will be recorded (inspections, requalification, and maintenance).

Contractor shall submit the periodicity of visit and controlled equipment requalification.

5.8 Risks connected with work at height

Should equipment use, maintenance or installation operations require elevated access, the Contractor shall provide protected access with guard rails in compliance with European standards **EN 14122-3**, if not, anchoring points compliant with European standards **EN 795**. In the latter case, technical documentation must make a very clear reference to it, in such a way as to implement related regulatory checks.

Where required, related personal protective equipment may be requested. They must be validated by the HSE Cell.

5.9 Risks connected with laser radiation

Lasers must have EC marking. The design, implementation and labelling of lasers must be compliant with standard **EN 60825**.

Should a risk exist beams must be automatically shut-off when the enclosure in which they are confined is opened (for example: opening of vacuum chamber, opening of mobile protectors, etc.).

Once completed by the Contractor, the following table should be inserted in Appendix A:

Type	Class			Power		If pulsed laser
------	-------	--	--	-------	--	-----------------

		Continuous or pulse	Wave length		Beam diameter before focusing	Energy	Length of pulses	Number of pulses

5.10 Risks related to sources of ionizing radiation (radioactive sources / electric generators of ionizing radiation, etc.)

If the equipment contains radioactive sources, or if it embeds an Electric Ionizing Radiation Generator, a description must absolutely be provided: type of source / characteristics / radiation / activity / kV / mA /

Please note: In this area, certain design obligations result solely from French regulations, including the decisions of the Nuclear Safety Authority (ASN)

The design of the device on the risk of ionizing radiation must meet an obligation of results, the specifications of which are given below.

Equipment design:

DECISION 2017-DC-591

The equipment must comply with DECISION 2017-DC-591 of the Nuclear Safety Authority "setting the minimum technical design rules to which the premises where electrical devices emitting X-rays are used must comply"

Full text available (in French) on request.

Warning: also applies to electrical devices emitting unwanted X-rays (for example: ion implanters, electron beam welding equipment, etc.)

In application of this decision:

- **Access restrictions**
When access is possible (door / hatch) :
 - Door open = X-ray emission not possible
 - Opening of the door = shutdown of X-ray production
- **Emergency stops**
An emergency stop button will be present near the control device and will cause:
 - A shutdown of X-ray production upon triggering
 - Holding of the stop order until it is rearmed
- **Risk light signalling:**
 - A light sign will be installed on each access
 - Power-on signalling
 - Radiation emission signalling
 - If several devices are installed: identification of the one in operation
 - In application of this criterion, a specific light tower will be installed outside the equipment at each access (doors);
 - orange color will indicate power on;
 - red color will indicate emission
- **Shutter**
 - The X-ray emission signalling will operate in connection with the position of the shutter and will flag the shutter open position.
 - In addition, a light signal will be present at the shutter level

Construction and test rules

FRENCH STANDARD NFC 74-100

Any equipment equipped with one or more X-ray generators must comply with the French standard **NFC 74-100 " RADIOLOGY EQUIPMENT X-Ray Apparatus Construction and tests REQUIREMENTS "**

The application of this standard is mandatory in France.

Certification assessment will be planned by the manufacturer on his site before delivery

If necessary please contact us to obtain the address of an accredited organization able to do this assessment.

The certificate of conformity regarding NFC 74-100 will be provided at delivery.

Radiation flux :

The manufacturer will certify that the emission measured at any point 10 cm from the equipment is less than 1μ Sv / hour (1 micro Sievert per hour)

5.11 Risks connected with noise

In reference to machinery directive **2006/42**:

"Machinery must be so designed and constructed that risks resulting from the emission of airborne noise are reduced to the lowest level taking account of technical progress and the availability of means of reducing noise in particular at source.

The level of noise emission may be assessed with reference to comparative emission data for similar machinery."

The noise level measurements will be performed and mentioned in the instruction manual in compliance 2006/42

The noise level generated by the equipment in its installation environment should be less than 70 dB (A).

If noise level is likely to exceed 70 dB (A), the Contractor will suggest quoted technical solutions of reduction: silent hardware, soundproof materials, soundproof covers on noise sources...

5.12 Risks connected with temperature

Hot surfaces: the temperatures of directly accessible hot surfaces must comply with standard requirements **NF EN ISO 13732-1**

Cold surfaces: The temperatures of cold surfaces directly accessible shall comply with the requirements of standard **NF EN ISO 13732-3** of 2008

WARNING: In the case of heating systems embedded in the machine

- The manufacturer must foresee the consequences of a malfunction of the control unit by installing a completely independent overheating safety device (sensor / regulator ...). This safety system will shut down the power and will require manual reset for restart (after fault clearing). The reliability of the cut-off system will be defined according to **EN 13849-1**
- The manufacturer must be able to define the consequences of a sudden and simultaneous complete interruption of the machine's "facilities": water / electricity / extraction hot air / nitrogen service ... when the system is at nominal temperature.

The equipment will have to support this scenario without generating a fire risk internal to the machine, nor any other risk (explosion ...)

In this scenario, if the temperature of the external enclosure of the equipment exceeds that of the equipment in normal mode, the Contractor will give the estimated temperature values and will consider them in the installation instructions (safety distances from the walls and other equipment).

5.13 Signaling

Signalling: risks shall be indicated on the machine using danger pictograms such as described in European regulations, accompanied as the case may be by an additional text;

In this case, the text must be labelled in French.

5.14 Intervention conditions on the CEA-LETI site

In collaboration with the Contractor and its possible sub-contractors, the CEA-LETI shall draft an overall prevention plan for installation, start-up and possibly development (JDP) services on equipment.

As loaning material is prohibited at the CEA, the Contractor and any subcontractors must provide safety materials needed to prevent specific risks generated by its intervention: PPE, CPE, breathing apparatuses, etc. It shall be responsible for replacement and repairs and, if required (without compensation on the part of CEA), it shall promote awareness and train its staff for use of equipment as per regulations. This material shall comply with regulations in force and shall be accompanied by a certificate of conformity.

The Contractor and its possible sub-contractors must provide all collective safety equipment used to prevent accidents due to works (marking work areas, marking traffic areas, marking handling and flyby areas, marking and installation of barriers around pits, level differences, etc.). It shall carry out and ensure removal of them as soon as the service no longer requires the presence of marking.

6 SUSTAINABLE DEVELOPMENT

6.1 Corporate Social Responsibility (CSR)

With an amount representing nearly 2.7 billion euros, CEA purchases are an integral part of societal and environmental issues.

The CEA monitors the quality and diversity of relations with its suppliers. It conducts a responsible purchasing policy based on three priority commitments:

- Create and maintain confidence-inspiring relations with its suppliers,
- Take into account the responsible dimension of its purchases,
- Contribute to the development of Small and Medium Enterprises (SMEs) and innovation.

Since 2004, it has been a signatory of the “responsible supplier relationship” charter and adheres to the SME Pact, a national support scheme for innovative SMEs.

The CEA's commitment to developing responsible purchasing cannot be made without taking this dimension into account by its suppliers.

The CEA is therefore counting on your proposals within the framework of this consultation to optimize the environmental impact of your services and develop the integration of people who are excluded from employment and the protected sector.

6.2 Sustainable development and development of the local economic fabric

As part of the “Sustainable Development” approach, CEA Grenoble is striving to improve its environmental performance and requires the cooperation of its suppliers in this respect.



In its proposal, the service provider shall present its corporate strategy as regards sustainable development and its specific improvement proposals concerning the work that covered by these Specifications.

Furthermore, as part of its “Plan Déplacement Entreprise” (“Corporate travel plan”), CEA Grenoble undertakes to reduce its environmental footprint.

The service provider shall cooperate with CEA Grenoble and undertakes to use zero emission vehicles as much as possible to meet the requirements mentioned in these Specifications.

Furthermore, LETI MINATEC is a pedestrian area, with regulated vehicular access.

Vehicles identified by the company's name may access the pedestrian area subject to CEA Grenoble's approval. All other vehicles shall be parked in the dedicated car park.

The recovery or disposal of waste created during the performance of the services is the responsibility of the supplier during the duration of the contract.

The supplier shall ensure that any operations, collection, transport, storage, sorting and disposal of waste created by the services subject to the contract are carried out to the sites likely to receive them, in accordance with the regulations in force.

6.3 Energy performance

As part of its ISO50001 "energy management" initiative, CEA Grenoble is working to improve its energy performance, and would like to be supported in this by its suppliers.



In its offer, the service provider presents its proposals for improvement specific to the services detailed in the present specifications.

CEA Leti asks the service provider to propose all equipment and solutions enabling to optimize and reduce as much as possible the energy consumption of the entire project, and to propose in its offer the energy saving certificates related to the project. »

7 EQUIPMENT DELIVERY CONDITIONS

The equipment and all the peripherals will be delivered clean and packaged in a serious and appropriate way. The transport platforms, pallets and packaging cases must be adapted to the weight and volumes of the elements in order to ensure safe a transport and avoid any dispute connected with improper packaging.

The following cleanliness requirements shall be fulfilled for the specific case of equipment intended to be installed in the clean rooms:

- very careful cleaning of all the subassemblies before shipment in order to remove any trace of shavings, hydrocarbons, grease or any other potential contaminant.
- packaging of the parts intended to be installed in the clean room under double film in order to perform progressive unwrapping while allowing a minimum amount of particles to contaminate the clean room. Peripherals intended to be installed in the basement may be packaged in single skin.
- likewise, all packages containing cable works, spare parts, various accessories required for assembling the equipment must be compatible with the clean rooms; wood, cardboard or traditional paper-type materials are prohibited; Contractor shall provide plastic-based non-contaminating wafer carriers (rigid or corrugated plastic cases for example).
- Filters of the environmental chambers and **FFUs shall not be delivered mounted on the equipment at delivery** to avoid any risk of particulate contamination and deterioration during handling and installation. Mounting remains the responsibility of the Contractor.

8 CONDITIONS FOR INSTALLING EQUIPMENT

Contractor shall enclose with its technical proposal the pre-installation document defined in **Appendix E**, then an installation file at the time of the installation.

It shall include all the installation conditions in particular the elements required in Paragraph 2: "instruction manual /installation" of Appendix E: Specifications pertaining to documents and manual to be provided with the equipment.

9 TRAINING & LEARNING

The Contractor undertakes to provide at no additional cost training covering the use of the equipment (operation and process development), and safety. Trainings for maintenance (hardware and software) will have to be proposed and quoted as an option. These trainings will be provided by a trainer of the Contractor and will end with a training certificate given to the trained personnel and the maintenance manager.

- **Training for use of the equipment**

After commissioning of the equipment, user training shall be provided on site for 10 to 12 people. This training shall cover use of the equipment in production mode and in engineering mode.

- **Safety training**

Contractor shall provide a complete safety training of the staff which will be appointed to operate the equipment.

In particular, this training must include:

- ✓ Training on the use conditions and contraindications of use,
- ✓ Information on the prevention devices implemented and residual risks,
- ✓ Training on the specific precautions and procedures to be complied with during adjustment and maintenance interventions,
- ✓ Training on the periodic functional check operations of the safety systems.

- **Level 1 maintenance training to be quoted as an option**

First level maintenance training will be provided [for 6 to 8 people](#) at CEA-LETI or on the Contractor's premises for maintenance and/or process staff upon acceptance.

The Contractor will provide a list and description of first level maintenance operations to be carried out on the equipment.

- **Advanced maintenance training to be quoted as an option**

The Contractor shall provide "advanced maintenance" training during the warranty period which will be carried out at the Contractor's training center. ([Training for 2 people](#)).

10 DOCUMENTATION

See **Appendix E**: "Specifications relating to the documents and manuals to be supplied jointly with the equipment". Each manual must be available in two paper version plus possible CD-ROM version.

Two sets of each manual shall be provided, one of the two sets shall be on clean room compatible paper.

From a statutory standpoint, the delivery of a document or publication in CD-ROM format only (no hardcopy version) is construed as non-conformity.

11 WARRANTY

11.1 Warranty conditions

Warranty shall start at the date of equipment acceptance for a duration of one year.

Warranty shall include corrective maintenance operations and cover all related costs: labour, spare parts, travels, shipments etc...

11.2 Support during warranty

During the warranty period, the Contractor agrees to provide on-site support within a maximum timeframe of 8 business hours after receiving an e-mail or a call from CEA-LETI.

Support shall be available for on-site intervention from 8am-6pm on weekdays.

11.3 Equipment performance indicators

- A) The definition of the down-time calculation used by the CEA-LETI is set out in Appendix C.
Up-time (%) = 100 – Down-time (%)
- B) During the warranty period:
Uptime > 95%
MTBF¹ > 1200h
MTTR² < 4h.
- C) Penalties during the warranty period
The up-time (see **Appendix C** "up-time definition") shall be assessed on a three-monthly basis.
Should one of the 2 parameters (Uptime or MTBF), recorded during the warranty period, not comply with specifications: the warranty period shall be automatically extended by a period of **3 MONTHS**.
During this extension, the Contractor shall perform all the corrective actions necessary to meet the specifications.
If, at the end of this warranty extension period, the specifications are still not met: the warranty shall be further extended by periods of 3 MONTHS until the specifications are met.

12 MAINTENANCE

12.1 Spare parts

12.1.1 List of spare parts:

In its bid, the Contractor shall include:

- A comprehensive list of spare parts;
- A comprehensive list of consumables needed to operate the equipment, with the functions, reference and price for each component.

These lists may be used as a basis for drawing up an agreement for the supply of spare parts and consumables.

The Contractor shall specify the standard delivery timeframe as well as the timeframe for an emergency situation.

12.1.2 Process-kit :

The equipment must be delivered with an additional process-kit per chamber to allow continuity of service after maintenance.

12.1.3 Storage area

The Contractor must specify in appendix A the floor space necessary for the storage of specific maintenance materials supplied with the equipment, including spare parts, tools, handling means etc:

- 1- Floor space required during installation phase

¹ Mean Time Between Failure

² Mean Time To Repair

2- Floor space required during normal use of the equipment

12.2 Maintenance contract

At the end of the warranty period, the CEA-LETI shall have the possibility of subscribing a maintenance contract. The Contractor shall commit to be able to perform preventive and corrective maintenance for each piece of Equipment after the warranty period has expired and for a minimum period of 10 years.

In the commercial proposal, the Contractor shall calculate the price of optional maintenance services, taking the following requirement levels into account:

- Full service including preventative maintenance, unlimited corrective maintenance, and all required spare parts. The Contractor should also commit to a defined up-time of the tool during this period. Unless otherwise stated, the performance of the tool during the Full Service contract will be that defined in the current « EQUIPMENT SPECIFICATIONS FORM ».
- Preventive maintenance plus corrective maintenance on request (hourly rates) complying with intervention and repair deadlines.

Further to the adjustment of CEA's needs with respect to maintenance, the maintenance contract may be implemented after the warranty period has expired further to negotiations.

12.3 Cost of ownership (COO)

Contractor shall provide the cost of ownership of system, including:

- Facilities consumption (gases, water -flows and required cooling capacity-, electricity, thermal load)
- Idle condition (includes consumables costs)
- Wafer move based (additional cost when tool is in production mode)
- Scheduled maintenance program and associated parts costs.

13 CHECKS & TESTS

The tests and checks of conformity for equipment subject of these specifications are broken down into six groups:

- ✓ At the factory
- ✓ Delivery
- ✓ Installation and commissioning
- ✓ Qualification
- ✓ Acceptance
- ✓ End of warranty

13.1 Checks and tests at the factory (Factory acceptance tests)

Factory acceptance test shall be performed at the Contractor's site based on the procedure defined beforehand and submitted for CEA-LETI approval. The Contractor will carry out the control in factory using its own wafers and carriers according to the references provided by the CEA. Tests of security devices shall be mandatorily included in factory acceptance: exhaust controllers, EMOs, door or panel switches...

A "Factory acceptance" report shall be drafted by CEA-LETI and signed by both parties to accept the Equipment and mention any restrictions. Contractor shall not be authorised to ship the equipment without signature of factory acceptance and solving restrictions before shipment.

13.2 Check upon delivery & at unpacking

Contractor shall submit the packing procedure for CEA-LETI acceptance. It shall at least specify breakdown of the packages, space requirement and associated instrumentation (example: accelerometer indicator).

The Contractor will ensure proper following of this procedure. If the delivery occurs in the presence of the Contractor (or his representative), the Contractor will check the integrity of the various packages, analyse the associated instrumentation and draft a “delivery” report (using their own documentation). Otherwise, the delivery countersigned by CEA-LETI shall be considered as the delivery report.

The packages destination must be indicated on boxes: basement or clean room.

The Contractor shall ensure that the equipment is correctly unpacked.

14 – Installation

The following chapters describes the main steps for installation preparation

14.1 Preparation

Contractor should be available at all time to assist CEA LETI in the preparation of the system installation

Part 1:

No later than 1 week after PO notification, Contractor must provide:

- Appendix H v0 - Implementation of the tool in the cleanroom & basement with its sub-equipment if not provided during the tender process
- System footprint - Dimension of all systems or sub systems
- Pre installation Manual

2 months after Po notification:

- Contractor must assist CEA LETI teams in order to validate definitive Appendix H v1 and Footprint/layout.

Part 2:

2 months after PO notification:

- Contractor must validate Appendix I with the CEA LETI safety officer be compliant with CEA risk management policy (Appendix I, Fire suppression analysis, extra safety detections common validation)
- Consolidate the need of sub assembly which might be supplied by CEA LETI

Part3:

6 months before system delivery Contractor must assist CEA LETI:

- for chassis conception (formal Contractor dimension and cut off validation is requested)
- for PIDs (fluids & electric) conception (same)
- commissioning planning

14.2 Installation

Basic Rules:

During the installation and as soon as possible, the Contractor will remove all waste and parts from the installation which are no longer required

All along the installation, Contractor must follow CEA LETI teams safety policy and must not open or start any fluid or source of energy without specific approval.

The following chapter describe the main steps for the installation & commissioning

14.2.0 System delivery & move in to final location:

After system delivery, system will be uncrated and moved in to its final location in the cleanroom by CEA-LETI or its subcontractor. Contractor must be present during this phase at the same time in cleanroom and in unloading dock

14.2.1 Tiers 0 - System mechanical assembly, system start Up

Basic Rules:

The Contractor shall use its own tools to perform equipment assembly, including handling and lifting tools that may be necessary.

During this phase, the Contractor will perform the equipment assembly, levelling.
Interconnections will be managed according to contract specification specified in the Appendix H

No energy will be present during this phase.

At the end of the Tier0:

- The machine and sub system will be energized.
- The Contractor must be present to acknowledge the power supply is meeting its specification

14.2.2 Tiers 1 - Final Hook Up and system start Up after power up

Basic Rules:

The Contractor must:

- Attend all the operations to install and connect the equipment to the facilities (fluids, extractions, etc.) and shall make sure that the latter are compliant with the Contractor's specifications. The contractor has the responsibility of the final connection from facilities to its equipment's
- Contractor must follow CEA safety policy and must not open or start any fluid or source of energy without specific approval.
- Make sure that the connections are compliant with the Contractor's specifications.
- For all the fluid connections (including effluents) or gas inter equipment or modules provided by the Contractor, the latter will carry out the marking and direction of these networks in accordance with European standard NF X 08-100 including pictograms SGH informing of the danger by printed solvent resistant laminated polyester adhesive stickers.
The valves will be equipped with color labels engraved out of PVC 8/10e fixed by adapted collars indicating their function.
- At the end of the installation, the Contractor will remove all waste and parts from the installation which are no longer required.

At the beginning of this phase, the system will be able to be powered Up.
The connection to Gas, Fluid, air extraction and Drain will be performed during this phase

The final gas connection to the system will be supervised by the contractor

The contractor will then:

- Perform the required hardware adjustment and calibration (robotics etc.) according to its system specification.
- Carry out checks on facilities which includes checking the various safety controls.
- Provide an "hardware report" commissioning which summarizes the progress of the above step and the result of the various controls. This report will confirm that the connection by the Contractor and standard safety tests are completed. The main safety elements concerned are: emergency stops, the extraction detection, leakage or gas detection, door contacts ... (Operation and connections)

Note:

The fluid connections to the equipment (process or chemical gases) will be made by CEA-LETI after receiving the "hardware report" described above from the Contractor and after the safety compliance inspection (described bellow) has been successfully completed.

At the end of the Tiers 1:

CEA-LETI will perform a safety compliance inspection (EC requirements).

The Contractor must be present during this inspection and will make all necessary documents available for the assessment of the equipment.

Depending on the anomalies, CEA-LETI may decide to suspend the commissioning operations pending remediation of the problems. Non-conformities noted correspond to non-compliance with the regulatory points. Any non-compliance must be resolved before the acceptance report can be signed.

All Anomalies and malfunctions will be promptly corrected by the Contractor no additional costs.

14.2.3 Tiers 2 - Contractor Equipment qualification & Contamination/ Handling test

This qualification procedure shall be performed in the presence of CEA-LETI authorised representatives.

The summary of these tests shall be countersigned by CEA-LETI (qualification summary report).

During this step,

- The contractor will make the handling test according to specification
- CEA LETI will test exhaust efficiency and air flow (FFUs)
- CEA LETI will perform a system contamination test and the mini environment
- The contractor will make its own system qualification according to system specification. A summary report might be provided and countersigned by CEA Leti at the end of the contractor test

In the case it is not under specification, the contractor will take the proper actions to get the systems under CEA LETI specification.

At the end of the Tiers 2:

The equipment is meeting the contractor specification test and the equipment is available for the CEA LETI process qualification.

The Contractor will remove all waste and parts from the installation which are no longer required.

14.2.4 Tiers 3 - CEA Process Qualification

During this phase, CEA-LETI ensures that the expected specifications for each process are met.

If these specifications are not met, even after the equipment supplier's intervention, it may result in the CEA-LETI refusing to accept the equipment or recording reservations in the CEA Equipment Acceptance Report.

Note: the contractor must be present during the test of the equipment

14.3 Acceptance

This acceptance recognises conformity of the equipment and transfer of ownership. The equipment warranty period shall start once the acceptance has been confirmed.

Acceptance shall be pronounced after:

- ✓ **Full delivery of the equipment**
- ✓ **The end of the installation and commissioning operations**
- ✓ **The qualification checks and tests successfully passed**
- ✓ **Authorisation from the installation manager at the home site**
- ✓ **Delivery of the documentation (see make up in APPENDIX E: Specifications pertaining to documents and manuals to be supplied with the equipment)**

A reception document without qualifications (*) will be signed between CEA-LETI and Contractor.

(*) A concession may possibly be granted for a reserve forming the subject of a detailed action plan for restoring compliance to the specifications subject of this document. If so, acceptance will be pronounced "with reservations"

Note: Only the report in CEA-LETI format, shall prevail to assert the associated payments with this stage and launch the warranty period.

14.4 End of warranty

The completion of the guarantee is pronounced at the end of the guarantee period under the following conditions:

- ✓ **Total removal of all qualifications noted during the acceptance**
- ✓ **No abnormalities detected**
- ✓ **Compliance of the equipment with the specifications during this period.**

In case of any abnormality, the Contractor will perform any work required to ensure the compliance of the equipment. If the functioning of the equipment is not satisfactory, the warranty period is automatically extended by a period described in the contract.

15 APPENDICES

APPENDIX A: Summary of Contractor's comments

Use the following template and ask the Contractor to fill it:

[APPENDIX A](#)

APPENDIX B: or general fluids to building

Appendix B: GENERAL FLUIDS IN BUILDING 52B Clean Room

General fluid distribution	Building 52B characteristics	Specific observations
Cooling Water (recommanded dimensionning velocity in the tube including in the exchanges : 1, 5m/s)	Material: PVC – Inox 316	Closed loop recycled water circuits→wastes water consumption prohibited Processing products : pH control corrosion inhibition, bioacide
	Outgoing pressure: 6 bars	
	Return pressure: ~ 0 bar	
	Outgoing temperature : 19°C	
	Conductivity: 200 microS/cm	
De Ionized Water (recommanded dimensionning velocity 1,5m/s)	pH: 7	EDI recycling of machines out let dealt with on a case by case basics depending on the risk analysis (chemical or particles pollution)
	Material: PVDF-HP	
	Pressure: 5 +/-0.5 bar	
	Temperature: 20°C +/-1°C	
	Resistivity: 15 Mohm.cm	
City Water	pH: 7	
	Particles < 50 /l @ 0.2 microns	
	Material: PVC	
	Pressure: 6 bar	
	Temperature : 12°C to 16°C	
Process Vacuum	Conductivity: 450 microS/cm	
	pH: 7.7	
	Calcium: 70 mg/l	
	Material: PVC-U	
	Relative pressure: ~ -880 mbar	
Nitrogen gas "service" (recommanded dimensionning velocity 20 m/s)	Material: stainless steel 316L Ra 0.8	Service nitrogen replace compressed air for all pneumatic uses : it is also used for vacuum pump ballasting.
	Relative pressure: 7 +/-0.5 bar	
	O2 < 1000 ppb	
	H2O < 1000 ppb	
Nitrogen gas "process" (recommanded dimensionning velocity 20 m/s)	Material: stainless steel 316L Ra 0,4	The nitrogen "process" is used for all which concerns the processes: purges, sweepings(scannings) of sieve(airlock,sieves,airlocks), ...
	Relative pressure: 7 ± 0.5 bars	
	O2 < 10 ppb	
	CO + CO2 + CnHm < 100 ppb	
	H2O < 10 ppb	
Compressed Dry Air	H2 < 10 ppb	
	Material: stainless steel 304L	
	Relative pressure: 7 +/-0.3 bar	
	H2O < 2 ppm	
	Temperature: 20°C +/-5°C	
General fluid distribution	Particles 0.2 microns< 2 /cubic ft	
	Building 52B characteristics	
	Specific observations	
	Material: stainless steel 316L Ra 0,4	
	Relative pressure : 6 bars	
Network argon (recommanded dimensionning velocity 20 m/s)	O2 < 100 ppb	
	N2< 100 ppb	
	H2O < 100 ppb	
	H2< 100 ppb	
	CO2 < 50 ppb	
	Cn Hm < 100 ppb	
Oxygen network	Material: : stainless steel 316L Ra 0,4	

	Relative pressure : 8 bars	
	H ₂ 0< 50 ppb	
	N ₂ < 100 ppb	
	CO ₂ < 100 ppb	
	CH ₄ < 100 ppb	
Helium network	Material: stainless steel 316L Ra 0,2	
	Relative pressure : 5,5 bars	
	O ₂ < 10 ppb	
	N ₂ < 100 ppb	
	H ₂ O < 20 ppb	
	CO ₃ CO ₂ < 50 ppb	
	H ₂ < 100 ppb	
	THC< 50 ppb	
Hydrogen network	Material : stainless steel 316L Ra 0,2	
	Relative pressure : 4,5 bars	
	O ₂ < 100 ppb	
	N ₂ < 200 ppb	
	H ₂ O < 20 ppb	
	CO ₃ CO ₂ < 50 ppb	
	THC< 50 ppb	
Waste collection	Building 52B characteristics	Specific observations
Acid-base drain	Material : PP	Reprocessed locally in a neutralizing plant - imperative limitation of discharge temperature at tool outlet --> less than 60°C
Fluorinated drain	Material : PP	Collected in a tank for reprocessing off site - imperative limitation of discharge temperature at tool outlet --> less than 60°C - limitation of dilution to reduce the volumes to be reprocessed --> no water venturi system but rather gravity draining.
Solvent drain	Material : stainless steel	Collected in a tank for reprocessing off site - limitation of dilution to reduce the volumes to be reprocessed --> no water venturi system but rather gravity draining or air venturi system.
Waste water drain	Material : PVC	

APPENDIX C: Definition of Availability

1. Planned time

The total planned time corresponds to the total hours of use for a reference period: 5 shifts - 7 days (168h/week).

2. Up-time definition

The basic formula for calculating the up-time is:

- Up-time (%) = 100 - Equipment down-time (%)

3. Down-time definition

The equipment down-time is the time during which the machine cannot be used for production according to the process specifications.

The equipment down-time is divided into:

- Scheduled down-time
- Unscheduled down-time

A) SCHEDULED DOWN-TIME

The scheduled down-time is the equipment shut-down time scheduled by the maintenance and production for preventive maintenance, for operations involving cleaning, modification, improvement, changing location, etc...

B) UNSCHEDULED DOWN-TIME

The unscheduled down-time is an unscheduled period during which the machine can not be used for production. Down-time must result from a failure proper to the equipment and not result from external elements (fluids, building, etc...).

This time does not take the user's imperfections into account :

- malfunctioning after incorrect use of the equipment (non-compliance with operating procedures),
- malfunctions resulting from the user's installations or structural or social problems.

4. Measuring up-time

Due to the up-time definition given above, measuring the up-time simply involves measuring the down-time.

5. Measuring down-time

A) START

Down-time starts from stoppage of production due to stopping of the machine, either deliberate or not, and from the agreement between the production and maintenance teams that production can no longer be performed with the specifications.

This moment is recorded on a document or in a file and is immediately notified to the Contractor (in case of failure) by telephone with confirmation by MAIL within 24h.

B) DURATION

Down-time covers:

- The initial period during which the operator performs troubleshooting to locate the cause of error, plus the waiting time of a maintenance person after a call to the Contractor's departments (in the case of a failure).
- The duration of the maintenance operation (repair / improvement / modification).
- The repair time resulting from waiting for spare parts.
- The time, after repair, to burn-in and check the equipment.
- The maintenance and process qualification time.

These different times must be noted and recorded accurately.

C) END

The end of equipment down-time takes place after the process has been qualified again. At this moment the machine is again in compliance with the specifications and can be used for production in agreement with the maintenance and process teams.

The different down-time states and times are consultable and can be supplied to the equipment Contractor on request from him.

MTBF definition

The MTBF is the mean up-time value in hours between two failure (the interrupt can be scheduled or unscheduled down-time). This mean value is calculated over 13 weeks and is the number of hours of up-time divided by the number of interrupts.

$MTBF = \text{Up-time (in hours)} / \text{number of interrupts}$

MTTR definition

Mean time to recover: mean time to put the machine back into a state of compliance, this state takes account of scheduled and unscheduled down-time and is averaged over 13 weeks.

$MTTR = \text{number of hours of down-time} / \text{number of interrupts}$

APPENDIX D: Specification for delivery of equipment subject to the European “machinery” Directive 2006/42/CE

Purpose: The aim of this document is to recall the application conditions of this directive as well as certain important technical points

1/ Reminder of the applicable regulation

The “machinery” directive is a European text transposed into the French law.

2/ Definition of a machine

A machine is “an assembly fitted with or intended to be fitted with a drive system other than directly applied human or animal effort consisting of linked parts or components, at least one of which move and which are joined together for a specific application...”

Consequently:

Any equipment complying with the definition will be designed and built in application with the “machinery” directive 2006/42

A machine is considered as “placed on the market for the first time”, “new” or “in the new condition” if it has not been used in a member state of the European Economic Community (EEC).

Consequently:

A second-hand machine from a non-EC country will be considered as new upon its entry into the EC.
The applicable regulation will be that in force at its date of entry.

3/ Reference standards

The presumption of conformity with regulatory requirements is provided by compliance with the provisions described in the harmonised standards mentioned above and circulated by AFNOR Tour de l'Europe 92049 Paris Cedex 7, France:

- specific standards to machinery
- general safety standards,
- standards pertaining to electrical equipment of machinery NF EN 60-204

Note: Compliance with standard 61010-1 does not give a presumption of compliance to the machinery directive

4/ Documents to be provided with the equipment subject to directive 2006/42

➤ **EC declaration of conformity**

2006/42 annex II:

“EC DECLARATION OF CONFORMITY OF THE MACHINERY

The declaration and translation thereof must be drawn up under the same conditions as the instructions [See Annexe I, Section 1.7.4.1, points a) and b)] and must be typewritten or else handwritten in capitals.

This declaration relates exclusively to the machinery in the state in which it was placed on the market and excludes components which are added and/or operations carried out subsequently by the final user.

The EC declaration of conformity must contain the following particulars:

- 1) business name and full address of the manufacturer and, where appropriate, its authorised representative;
- 2) the name and address of the person authorised to compile the technical file, who must be established in the community;
- 3) description and identification of the machinery, including generic denomination, function, model, type, serial number and commercial name;
- 4) a sentence expressly declaring that the machinery fulfilled all the relevant provisions of this directive and where appropriate a similar sentence declaring the conformity with other directives and/or relevant provisions with which the machinery complies. These references must be those of the text published in the official journal of the European Union;
- 5) where appropriate, the name, address and identification number of the notified body which carried out the EC type-examination referred to in Annexe IX and the number of the EC type-examination certificate;
- 6) where appropriate, the name, address and identification number of the notified body which approved the full quality assurance system referred to in Annexe X;
- 7) where appropriate, a reference to the harmonised standard used as referred to in Article 7, Paragraph 2;
- 8) where appropriate, the reference to other technical standards and specifications used;
- 9) the place and date of the declaration;
- 10) identification and signature of the person empowered to draw up the declaration on behalf of the manufacturer or his authorised representative.”

➤ **An instruction manual**

An instruction manual shall be drawn up in compliance with Paragraph 1.7.4 of Directive 2006/42; see our Appendix E

5/ Marking on the equipment (2006/42 – 1.7.3)

“I. – Each machinery must be marked visibly, legibly and indelibly with the following minimum particulars:

- a) The business and full address of the manufacturer;
 - b) Designation of the machinery;
 - c) The CE marking;
 - d) The designation of series or type;
 - e) The serial number if any;
 - f) The year of construction, that is, the year in which the manufacturing process is completed. It is prohibited to predate or postdate the machinery when affixing the CE marking.
- Furthermore, machinery designed and constructed for use in a potentially explosive atmosphere must be marked accordingly.

II. – Machinery must bear full information relevant to its type and essential for safe use. Such information is subject to the requirement set out in Section 1.7.1.

III. – Where a machine part must be handled during use with lifting equipment, it must be indicated legibly, indelibly and unambiguously.”

APPENDIX E: Specification relating to documents and manuals to be provided with the equipment

1. Purpose

This appendix is intended to define the documentation to be delivered by the Contractor with the equipment (content, language, delivery schedule).

The documentation to be delivered by the equipment must meet current regulations.

The CEA-LETI / LETI specifications include the statutory requirements.

These obligations depend on whether the equipment is subject to the machine directive 2006/42 / EC.

2. Supply of an equipment item subject to machinery directive 2006/42/EC (e.g. 98/37/EC)

2.1. Regulatory obligations

2.1.1. Instruction manuals

The regulations describe all the elements relating to the instructions that must be supplied with the equipment (content, language etc.).

This information is included in Annex I to Directive 2006/42 transposed into French law (Annex I of Book II of the Labour Code)

Content

The instruction manual will be drafted in compliance with Paragraph 1.7.4. of this appendix and where applicable Paragraphs 3.6.3 (moving machines) and 4.4 (lifting systems).

2006/42 - 1.7.4 .2: Content of the instruction manual:

“Each instruction manual must contain, where applicable at least the following information:

- a) The business name and full addresses of the manufacturer;
- b) The designation of the machinery as marked on the machinery itself except for the serial number in compliance with Paragraph 1.7.3;
- c) The EC declaration of conformity or a document setting out the contents of the EC declaration of conformity, showing the particulars of the machinery, not necessarily including the serial number and the signature;
- d) General description of the machinery;
- e) The drawings, diagrams, descriptions and explanations necessary for the use, maintenance and repair of the machinery and for checking its correct functioning;
- f) A description of the workstation(s) likely to be occupied by operator;
- g) A description of the intended use of the machinery;
- h) Warnings concerning ways in which machinery must not be used that experience has shown might occur;
- i) Assembly, installation and connection instructions, including drawings, diagrams and the means of attachment and the designation of the chassis or installation on which the machinery is to be mounted;
- j) The instructions relating to installation and assembly for reducing noise or vibration;
- k) The instructions for putting into service and use of the machinery and, if necessary instructions for the training of operator;

- l) The information about the residual risks that remain despite the inherent safe design measures, safe-guarding and complementary protective measures adopted;
- m) Instructions on the protective measures to be taken by the users, including, where appropriate, the personal protective equipment to be provided;
- n) The essential characteristics of tools which may be fitted to the machinery;
- o) The conditions in which the machinery meets the requirement of stability during use, transportation, assembly, dismantling when out of service, testing or foreseeable breakdown;
- p) Instructions with a view to ensuring that transport, handling and storage operations can be made safely, giving the mass of the machinery and of its various parts where these are regularly to be transported separately;
- q) The operating method to be followed in the event of accident or breakdown; if a blockage is likely to occur, the operating method to be followed so as to enable the equipment to be safely unblocked;
- r) The description of the adjustment and maintenance operations that should be carried out by the user and the preventive maintenance measures that should be observed;
- s) Instructions designed to enable adjustment and maintenance to be carried out safely, including the protective measures that should be taken during these operations;
- t) The specifications of the spare parts to be used, when these affect the health and safety of operators;
- u) The following information on airborne noise emissions:
- the A – weighted emission sound pressure level at workstations, where this exceeds 70 dB (A); if this level is less than or equal to 70 dB (A), this fact must be indicated;
 - the peak C - weighted instantaneous sound pressure value at workstations where this exceeds 63 Pa (130 dB in relation to 20 µPa);
 - the A – weighted sound power level emitted by the machinery, where the A – weighted emission sound pressure level at workstations exceeds 80 dB (A)."

Language

"All machinery must be accompanied by instructions in French.

The instructions manual accompanying the machinery must be either an original instruction manual or a translation of the original manual in which case, the translation must be accompanied by the original instruction manual."
(Transposition of 2006/42 1.7.4)

"The instruction manual is drafted in French and may be in one or more official Community languages. The word original instruction manual must appear on the language version(s) verified by the manufacturer. Where no original instruction manual exists in French, a translation into this language must be provided by the manufacturer or by the person bringing the machinery into France. This translation must bear the words translation of the original instruction manual." **(Transposition of 2006/42 1.7.4.1)**

Consequently, the following will be provided:

- The instruction manual in its original version drafted in one of the EC languages, in any case
- The instruction manual translated in French (if the original version was drafted in another language than French) in the case where this obligation is incumbent upon the Contractor.

2.1.2. Maintenance manual

“By way of exception, the maintenance instructions intended for use by specialised personnel mandated by the manufacturer may be supplied in only one community language which the specialised personnel understand.”
(2006/42- 1.7.4)

2.2. Specific specifications at CEA/LETI

Contractor shall mandatorily provide:

- The instruction manual as described in 2.1.1 and specified in 2.2.1.
- The maintenance manual as described in 2.2.2.
- A file of all elements that were tested and validated during startup and adjustments made in connection with facilities for each fluid. This file will also include factory tests and calculation sheet for parts of the facility used for their selection during design (heat exchangers, flow rates, sections of pipes that are inside equipment).
- These instructions should be delivered with the equipment except the installation section of the instructions which should be received by CEA-LETI / LETI, together with the Contractor's offer.

2.2.1. Instruction manual

The instruction manual shall correspond to the machine delivered and contain in particular the following chapters:

- Handling
- Assembly – Disassembly
- Installation
- Commissioning
- Adjustment
- Use
- Maintenance (1st level)

Handling

This chapter shall deal with the conditions for handling the equipment: lifting or bearing points, miscellaneous precautions to be taken during handling. It shall give indispensable information such as the weight in kilograms. It shall highlight the counter-indications such as for example shocks, tilting etc...

If the equipment is comprised of different parts, the same information shall be given for handling each part.

Assembly - Disassembly

This chapter shall specify if applicable the order of the operations, the precautions to be taken, and the tooling required.

Installation

This part shall contain all the specifications necessary for installation and connection of the machine on the CEA-LETI premises. A copy of this part shall be sent to the CEA/LETI/Department concerned, before the equipment is delivered. This chapter shall contain in particular the following information :

- For the equipment and its sub-assemblies: dimensions in mm, weight (in kg), dimensional drawing mentioning the connection points to the different networks.
- Environment required: dust content, hygrometry, vibrations, sensitivity to vibrations and electromagnetic radiation, extractions to be provided etc...
- Nature of the floor: resistance required with respect to the weight of the machine, flatness.
- Electricity: Voltage, Power, features of the power supply transformer if applicable.
- Pneumatics (compressed air): pressure, quality.
- Fluids: Type, pressure, flowrate, temperature, characteristics.
- Gas: Type, pressure, quality.
- Counter-indications for installation, nuisances introduced by the equipment.

All these parameters shall be accompanied by a tolerance.

Commissioning

Even if commissioning is performed by the Contractor, this chapter shall set out the procedure to be followed for commissioning of the equipment (prior checks, start-up procedure etc.).

Adjustments

A procedure shall be provided to perform tuning/adjustments within the scope of normal everyday use of the machine.

Use

This chapter shall contain:

- The conditions of use scheduled by the manufacturer.
- The definition of the workstation(s) occupied by the operator(s).
- A presentation of the equipment enabling identification of the different parts (photos, diagrams) explaining the function of each part, particularly of the control and safety means.
- A description of the running sequence of the operations performed by the equipment. All the processes available on the equipment shall be described along with the nature and influence of each "process" parameter.
- An operating mode describing the details of the operations to be performed to process a sample, a batch (for example). It shall contain the learning instructions.

CAUTION

In the case of an automatic machine, the operation mode shall not be limited to necessarily succinct description of loading/unloading of a sample or a batch (for example) but shall enable the parameters of the standard functions to be adjusted and the alarm messages to be understood.

In the case where man/machine dialogue takes place via keyboard + monitor or touch-sensitive screen, the following information provided by the manual shall enable :

- the general software architecture (maintenance part / engineering part / operator part for example) to be understood,
- navigation between the different parts,
- the parameters of a task performed by the machine and influencing the "process" (for example: speed, time, pressure, power etc.) to be adjusted, these operations falling within the scope of normal use of the machine in a research environment,
- the results or "process" running monitoring tables to be accessed,
- the alarm messages to be understood and interpreted.

To achieve this result, the manual shall reproduce the main tables displayed on the monitor. Each table shall be accompanied by comments on the actions to be performed, on the nature of the information given.

Maintenance

The object of this chapter is to enable troubleshooting to be performed and certain problems of low complexity to be resolved. It involves 1st level maintenance.

CAUTION

All the chapters of this manual shall be drafted integrating the safety warnings so that the operations described can be carried out without any risks.

This appendix is fully applicable even if supply of the equipment is accompanied by personnel training.

The potential users of this manual are technicians or engineers in charge of tuning the "processes". This shall be taken into account in the choice of the information supplied.

The equipment shall only be accepted after a detailed examination of the documents provided.

2.2.2. Maintenance manual

It shall contain :

- a presentation of the machine enabling the component parts to be located (photos),
- the interconnection diagrams between the different sub-assemblies,
- the electrical power diagrams, control diagrams, and interconnection diagrams between the different parts, the printed circuit board diagrams,
- the diagrams of the pneumatic and hydraulic circuits,
- the mechanical construction drawings (exploded views),
- the spare parts list,
- the specific documentation of apparatuses integrated in the machine such as automatic controllers, regulators, RF and micro-wave generators.
- the programs and programming tools associated to automatic controllers,
- the list of periodic checks to be performed,
- the list of preventive maintenance operations to be performed with the list of consumables associated with the operation,
- a troubleshooting guide,
- the access modes to the software maintenance parts, if applicable, and the back-up procedures.

3. Supply of equipment not subject to the machinery directive: Specifications of CEA/LETI

The special specifications of CEA/LETI [(§ 2.2)] of this document apply.

APPENDIX F: Selection of protection against risks connected with moving parts Characteristics required for guards and protective devices

Abstract of machinery directive 2006/42

1.2.5. Selection of control or operating modes

The control or operating mode selected must override all other control or operating modes, with the exception of the emergency stop.

If machinery has been designed and constructed to allow its use in several control or operating modes requiring different protective measures and/or work procedures, it must be fitted with a mode selector which can be locked in each position. Each position of the selector must be clearly identifiable and must correspond to a single operating or control mode.

The selector may be replaced by another selection method which restricts the use of certain functions of the machinery to certain categories of operator.

If, for certain operations, the machinery must be able to operate with a guard displaced or removed and/or a protective device disabled, the control or operating mode selector must simultaneously:

- disable all other control or operating modes,
- permit operation of hazardous functions only by control devices requiring sustained action,
- permit the operation of hazardous functions only in reduced risk conditions while preventing hazards from linked sequences,
- prevent any operation of hazardous functions by voluntary or involuntary action on the machine's sensors.

If these four conditions cannot be fulfilled simultaneously, the control or operating mode selector must activate other protective measures designed and constructed to ensure a safe intervention zone.

In addition, the operator must be able to control operation of the parts he is working on from the adjustment point.

1.3.8. Choice of protection against risks arising from moving parts

Guards or protective devices designed to protect against risks arising from moving parts must be selected on the basis of the type of risk. The following guidelines must be used to help to make the choice.

1.3.8.1. Moving transmission parts

Guards designed to protect persons against the hazards generated by moving transmission parts must be:

- either fixed guards as referred to in section 1.4.2.1, or
- interlocking movable guards as referred to in section 1.4.2.2.

Interlocking movable guards should be used where frequent access is envisaged.

1.3.8.2. Moving parts involved in the process.

Guards or protective devices designed to protect persons against the hazards generated by moving parts involved in the process must be:

- either fixed guards as refer to in Section 1.4.2.1, or
- interlocking movable guards as refer to in Section 1.4.2.2, or;
- protective devices as refer to in Section 1.4.3, or
- a combination of the above.

However, when certain moving parts directly involved in the process cannot be made completely inaccessible during operation owing to operations requiring operator intervention, such parts must be fitted with:

- fixed guards or interlocking movable guards preventing access to those sections of the parts that are not used in the work;

and

- adjustable guards as referred to in Section 1.4.2.3 restricting access to those sections of the moving parts where access is necessary.

1.3.9. Risks of uncontrolled movements.

When a part of the machinery has been stopped, any drift away from the stopping position, for whatever reason other than action on the control devices, must be prevented or must be such that it does not present a hazard.

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1.4. Required characteristics of guards and protective devices.

1.4.1. General requirements.

Guards and protective devices must:

- be of robust construction;
- be securely held in place;
- not give rise to any additional hazard;
- not be easy to bypass or render non-operational;
- be located at an adequate distance from the danger zone;
- cause minimum obstruction to the view of the production process;
- enable essential work to be carried out on the installation and/or replacement of tools and for maintenance purposes by restricting access exclusively to the area where the work has to be done, if possible without the guard having to be removed or the protective device having to be disabled.

In addition, guards must, where possible protect against the ejection or falling of materials or objects and against emission generated by the machinery.

1.4.2 Special requirement for guards

1.4.2.1. Fixed guards.

Fixed guards must be fixed by systems that can be opened or removed only with tools.

Their firing systems must remain attached to the guards or to the machinery when the guards are removed.

Where possible, guards must be incapable of remaining in place without their attachment.

1.4.2.2. Interlocking movable guards.

1 Interlocking movable guards must be designed and constructed:

- to remain attached where possible to the machinery when opened;
- they can be adjusted only by means of an intentional action.

2 Interlocking movable guards must associated with an interlocking device that:

- prevents the start of hazardous machinery functions until they are closed,
And
- gives a stop command whenever they are no longer closed.

3 Where it is possible for an operator to reach the danger zone before the risk due to the hazardous machinery function has ceased, movable guards must be associated with a guard locking device in addition to an interlocking device that:

- prevents the start of hazardous machinery functions until the guard is closed and locked,
And
- keeps the guard closed and locked until the risk of injury from the hazardous machinery functions has ceased.

4 Interlocking movable guards must be designed in such a way that the absence or failure of one of their components prevent starting or stops the hazardous machinery functions.

1.4.2.3. Adjustable guards restricting access.

Adjustable guards restricting access to those areas of the moving parts strictly necessary for the work must be:

- adjustable manually or automatically, depending on the type of work involved;
- readily adjustable without the use of tools.

1.4.3. Special requirements for protective devices.

Protective devices must be designed and incorporated into the control system in such a way that:

- moving parts cannot start up while they are within the operator's reach;
- persons cannot reach moving parts while the parts are moving,
And
- the absence or failure of one of their components prevents starting or stops the moving parts.

Protective devices must be adjustable only by means of an intentional action.

APPENDIX G: Transfer and handling of wafers

1 – Applicable SEMI standards

Equipment must be compliant with following SEMI Standards:

	<i>SEMI Standard</i>
G1.1	SEMI E15.1 — Specification for 300 mm Tool Load Port
G1.2	SEMI E47.1 — Provisional Mechanical Specification for Boxes and Pods Used to Transport and Store 300 mm Wafers
G1.3	SEMI E57 — Mechanical Specification for Kinematic Couplings Used to Align and Support 300 mm Wafer Carriers
G1.4	SEMI E62 — Provisional Specification for 300 mm Front-Opening Interface Mechanical Standard (FIMS)
G1.5	SEMI E63 — Mechanical Specification for 300 mm Box Opener/Loader to Tool Standard (BOLTS-M) Interface
G1.6	SEMI E64 — Specification for 300 mm Cart to SEMI E15.1 Docking Interface Port
G1.7	SEMI E72 — Specification and Guide for 300 mm Equipment Footprint, Height, and Weight
G1.8	SEMI E103 — Provisional Mechanical Specification for a 300 mm Single-Wafer Box System that Emulates a FOUP
G1.9	SEMI E110 - Guideline for Indicator Placement Zone and Switch Placement Volume of Load Port Operation Interface for 300 mm Load Ports
G1.10	SEMI E111 - Provisional Mechanical Specification for a 150 mm Reticle SMIF Pod (RSP150) Used to Transport and Store a 6 Inch Reticle. (if applicable)

Other applicable standards

- Classification of air cleanliness: standard ISO 14644-1
- Metrology and test methods: standard ISO 14644-3
- Protection of electronic devices against electrostatic discharges: IEC 61340-5-1
- Mini-environment : IEST- RP-CC028.1
- Control of mini-environments: QM 07.08.011
- Check of mini-environments: QII 07.08.004
- Particle inspection of the air: QM 07.08.001
- Metrological inspections: QM 07.08.004

2. Handling Device

Loadport:

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	<i>Loadport</i>	<i>Objective</i>
G2.1	Loadport Kinematic coupling pins ground resistivity value	< 100 kohm
G2.2	Maximum wafer insertion temperature in FOUP	< 100 °C
G2.3	Maximum FOUP environment continuous temperature	80°C
G2.4	Inserted wafers in FOUPs are dry	No droplet
G2.5	Maximum static charge during wafers FOUPs insertion	< 100V cm
G2.6	Maximum delay between docking request and end docking movement	< 10s
G2.8	A "load" push button (one position stable) is placed at the right front side of FOUP load as figure 1	Y

APPENDIX H: Datasheet for tool installation

Use the following template and ask the Contractor to fill it:

APPENDIX H



ANNEXE H : Datasheet for tool installation

- 1) The datasheet informations allows CEA-LETI to design the fluid PID and the electrical PID.
- 2) These PIDs are then sent for verification and approval to the Contractor.
- 3) Hook Up and Fit Up will start after the official validation of PIDs by the Contractor.

Equipement Model :

List of Equipments & sub-equipments

Name	Location (Fab or sub-fab)	Type (Chiller, pump...)	Model	Dimensions (L x w x h) in mm	Weight (Kg)	Supplied by
Chiller 1	Sub-Fab	Heat Exchanger	NESLAB HX-150	500 x 600 x 900	400	Contractor
Pump 1	Sub-Fab	Pump	iHu 600	300 x 900 x 800	200	CEA-LETI
Mainframe	Fab	Mainframe	XXXX	2500 x 1300 x 2600	2500	Contractor

EXAMPLE

Facilities requirements				Connection		Consumption (e)				Pressure (bar) at the connection on the tool		Temp (° C)		Purity		
Fluid (a)	From	To	Description (b)	ID (c.)	Size (d)	Type	Min	Max	Average	Min	Max	Min	Max		Supplied by	Comments (ex: max length...) (f)
N2S	Facilities	Mainframe CH A	N2 Purge	G1	1/4"	VCRM	15	50	25	2.5	5	N/A	N/A	N/A	CEA-LETI	EXAMPLE
Glycol	Chiller 1	Mainframe CH A	Chilled Water	F1	3/8"	swg	10	20	12	2	3	15	18	N/A	Contractor	installed by CEA-LETI EXAMPLE
BCG	Facilities	Mainframe CH A	BCG proces	J2	1/4"	VCRM	1	2	1.2	1	1.3	N/A	N/A	N50	CEA-LETI	Purity : N50

The datasheet information allows CEA-LETI to design the fluid PID and the electrical PID (PID = Piping and Instrumentation Diagram).

These PIDs are then sent for verification and approval to the equipment Contractor.

Hook Up and Fit Up will start after the official validation of PIDs by the Contractor.

APPENDIX I: Risk Identification Sheet

Use the following template and ask the Contractor to fill it:

APPENDIX I

cea leti		DPFT					
APPENDIX I : Risk Identification Sheet							
EQUIPEMENT REFERENCE & NAME :							
REFERENCE OF SAFETY DOCUMENTS PROVIDED							
EC Compliance certificate		☐		Safety information and requirements in French		☐	
RISK IDENTIFICATION							
Chemical risk : ☐							
Product name		Physical state (solid, liquid, gas)		DANGEROUSNESS		Usage concentration	
Explosion risk : ☐							
Under-pressure elements (bulb, pressure tank, ...):				Pressure :		Volume :	
Thermal risk : ☐							
Heating elements :				Temperature :			
Electrical risk : ☐							
Maximum voltage :				AC :		DC:	
Risk from ionising radiations : ☐							
Sealed radioactive material ☐				Presence of X-rays ☐		Open source radioactive material ☐	
Risk from non-ionising radiations : ☐							
UV ☐		Infrared ☐		High frequency ☐		Electromagnetic ☐	
Microwaves ☐		Permanent magnet ☐		Laser ☐ Category (1-2-3-4) :			
Risk from handling during maintenance: ☐							
Manual handling ☐		Mechanical handling ☐		Handling device :			
Other risks :							
Equipment internal detections :							
Fire detection ☐				Leak detection ☐			
Gas detection ☐				Extraction control ☐			
Comments :							

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APPENDIX J: SECS/GEM Compliance

Use the following template and ask the Contractor to fill it:

[APPENDIX J](#)

APPENDIX K: Pedestal specification

Use the following template and ask the Contractor to fill it:

[APPENDIX K](#)